

DRV8317 三相 PWM 电机驱动器

1 特性

- 三相 BLDC 电机驱动器
 - 用于缓解 EMI 的可配置压摆率
 - 可编程增益电流检测
 - 支持高达 200kHz 的 PWM 频率
 - 集成击穿保护
- 4.5V 至 20V 工作电压
 - 24V 绝对最大电压
- 高输出电流能力
 - 5A 峰值电流驱动能力
- 低导通状态电阻 MOSFET
 - $T_A = 25^\circ\text{C}$ 时的 $R_{DS(ON)}$ (HS + LS) : 130m Ω (典型值)
- 超低静态电流睡眠模式
 - $V_{VM} = 12\text{V}$ 、 $T_A = 25^\circ\text{C}$ 时为 3 μA (最大值)
- 多种控制接口选项
 - 6x PWM 控制接口
 - 3x PWM 控制接口
- 集成式电流检测
 - 无需外部电流检测电阻
 - 三相电流检测输出
- SPI 和硬件器件型号
 - 10MHz SPI 接口型号, 可实现灵活性
 - 引脚可配置型号, 可实现简单性
- 支持 1.8V、3.3V 和 5V 逻辑输入
- 内置 $3.3\text{V} \pm 4.5\%$ 、80mA LDO 稳压器
- 集成保护特性
 - VM 欠压锁定 (UVLO)
 - VM 过压保护 (OVP)
 - 电荷泵欠压 (CPUV)
 - 过流保护 (OCP)
 - 过热警告和关断 (OTW/OTS)
 - 故障条件指示引脚 (nFAULT)

2 应用

- 无刷直流 (BLDC) 电机模块
- 空气净化器
- 洗碗机泵
- 扫地机器人
- 洗衣机和烘干机泵
- 无人机和手持设备万向节
- 笔记本电脑、台式机和服务器风扇
- 咖啡机

3 说明

DRV8317 提供三个集成 MOSFET 半桥, 用于驱动采用 5V、9V、12V 或 18V 直流电源轨或 2 节到 4 节串联电池的三相无刷直流 (BLDC) 电机。该器件提供集成三相电流检测功能, 无需再使用外部检测电阻。DRV8317 具有集成 LDO, 可提供稳压 3.3V 电源轨, 能够为 MCU、逻辑电路、霍尔传感器等外部负载提供高达 80mA 的电流。

DRV8317 提供了可配置的 6x 或 3x PWM 控制方案, 可用于使用外部微控制器实施有传感器或无传感器磁场定向控制 (FOC)、正弦控制或梯形控制。DRV8317 能够驱动高达 200kHz 的 PWM 频率。DRV8317 可通过 SPI (DRV8317S) 或引脚 (DRV8317H) 进行高度配置。PWM 模式、压摆率、电流检测增益是部分可配置的特性。

DRV8317 集成了多种保护特性, 包括电源欠压锁定 (UVLO)、过压保护 (OVP)、电荷泵欠压 (CPUV)、过流保护 (OCP)、过热警告 (OTW) 和过热关断 (OTS), 目的是在出现故障事件时保护器件、电机和系统。故障状态通过 nFAULT 引脚指示。

器件型号信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
DRV8317S ⁽²⁾	WQFN (36)	5.00mm × 4.00mm
DRV8317H	WQFN (36)	5.00mm × 4.00mm

- (1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。
 (2) 器件仅为预发布版。

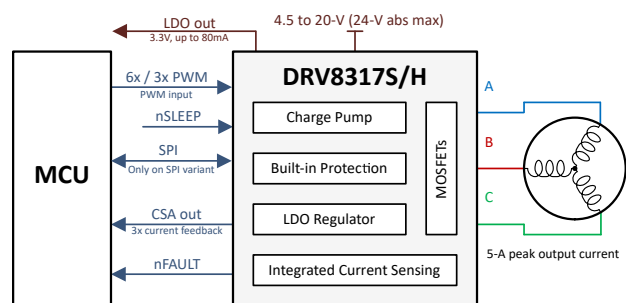


图 3-1. DRV8317S/H 简化原理图



Table of Contents

1 特性	1	8.6 DRV8317 Registers.....	39
2 应用	1	9 Application and Implementation	57
3 说明	1	9.1 Application Information.....	57
4 Revision History	2	9.2 Typical Applications.....	58
5 Device Comparison Table	3	9.3 Alternate Applications.....	61
6 Pin Configuration and Functions	4	10 Power Supply Recommendations	62
7 Specifications	6	10.1 Bulk Capacitance.....	62
7.1 Absolute Maximum Ratings.....	6	11 Layout	63
7.2 ESD Ratings.....	6	11.1 Layout Guidelines.....	63
7.3 Recommended Operating Conditions.....	6	11.2 Layout Example.....	64
7.4 Thermal Information.....	7	11.3 Thermal Considerations.....	65
7.5 Electrical Characteristics.....	7	12 Device and Documentation Support	66
8 Detailed Description	15	12.1 支持资源.....	66
8.1 Overview.....	15	12.2 Trademarks.....	66
8.2 Functional Block Diagram.....	16	12.3 静电放电警告.....	66
8.3 Feature Description.....	18	12.4 术语表.....	66
8.4 Device Functional Modes.....	36	13 Mechanical, Packaging, and Orderable Information	66
8.5 SPI Communication.....	37		

4 Revision History

DATE	REVISION	NOTES
April 2022	*	Initial release

5 Device Comparison Table

DEVICE	PACKAGES	INTERFACE
DRV8317S	36-pin WQFN (5-mm x 4-mm)	SPI
DRV8317H		Hardware (Pin)

表 5-1. DRV8317S vs DRV8317H Configuration Comparison

Parameters	DRV8317S	DRV8317H
PWM control mode	PWM_MODE (4 settings)	MODE pin (2 settings)
Slew rate	SLEW_RATE (4 settings)	SLEW pin (4 settings)
Current sense amplifier gain	CSA_GAIN (4 settings)	GAIN pin (4 settings)
OCP blanking time	OCP_TBLANK (4 settings)	Fixed to 0.7- μ s
OCP deglitch time	OCP_DEG (4 settings)	Fixed to 0.6- μ s
OCP mode	OCP_MODE (4 settings), Configurable retry time	5-ms automatic retry
Dead time	Fixed based on SLEW_RATE setting	Fixed based on SLEW pin setting
Propagation delay	Fixed based on SLEW_RATE setting	Fixed based on SLEW pin setting
Driver delay compensation	DLYCMP_EN (2 settings)	Disabled
Spread Spectrum Clock for internal oscillator	SSC_DIS (2 settings)	Enabled
VM under voltage lockout	VM under voltage protection always enabled. VM under voltage protection mode set by UVP_MODE (2 settings); configurable retry time using SLOW_TRETRY and FAST_TRETRY.	VM under voltage protection always enabled. Auto-retry mode for VM under voltage with 5-ms retry time.
VIN_AVDD, AVDD under voltage lockout	VIN_AVDD and AVDD under voltage protection always enabled. Device resets on VIN_AVDD or AVDD under voltage.	VIN_AVDD and AVDD under voltage protection always enabled. Device resets on VIN_AVDD or AVDD under voltage.
CP under voltage lockout	CP under voltage protection always enabled. CP under voltage protection mode set by UVP_MODE (2 settings); configurable retry time using SLOW_TRETRY and FAST_TRETRY.	CP under voltage protection always enabled. Auto-retry mode for CP under voltage with 5-ms retry time.
VM over voltage	OVP_MODE (2 settings); configurable retry time using SLOW_TRETRY and FAST_TRETRY	5-ms automatic retry
SPI fault	SPIFLT_MODE (2 settings)	N/A
FET over temperature warning (OTW_FET)	Enable/disable using OTW_FET_EN. If enabled, over temperature warning is reported on nFAULT pin and OTW_FET bit in OT_STS register.	Disabled
FET over temperature shutdown (OTS_FET)	OTF_MODE (2 settings); configurable retry time using SLOW_TRETRY and FAST_TRETRY	5-ms automatic retry

6 Pin Configuration and Functions

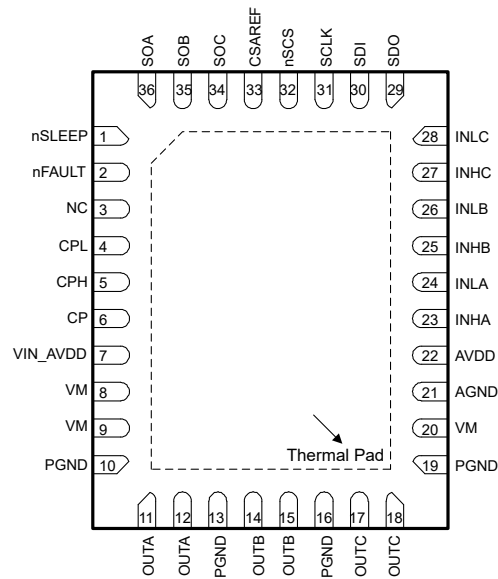


图 6-1. DRV8317S 36-Pin WQFN With Exposed Thermal Pad Top View

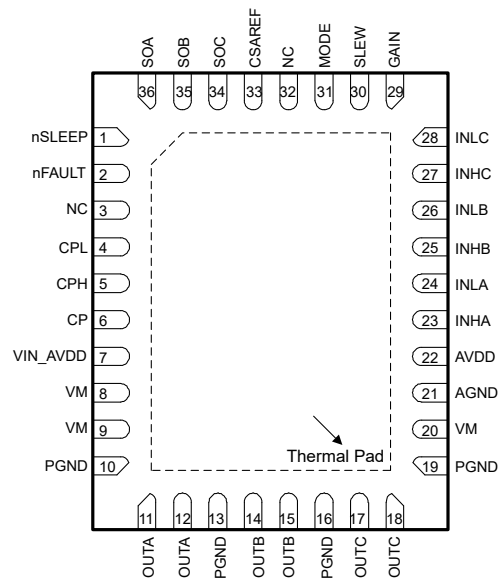


图 6-2. DRV8317H 36-Pin WQFN With Exposed Thermal Pad Top View

表 6-1. Pin Functions

PIN NAME	36-pin package		TYPE ⁽¹⁾	DESCRIPTION
	DRV8317S	DRV8317H		
AGND	21	21	GND	Device analog ground. Connect to a separate ground plane. ²
AVDD	22	22	PWR O	3.3V regulator output. Connect a X5R or X7R, 2.2- μ F (no load) or 4.7- μ F (up to 80mA load), 6.3-V ceramic capacitor between the AVDD and AGND pins. This regulator can source up to 80 mA for external loads.
CP	6	6	PWR	Charge pump output. Connect a X5R or X7R, 1- μ F, 16-V ceramic capacitor between the CP and VM pins.
CPH	5	5	PWR	Charge pump switching node. Connect a X5R or X7R, 100-nF, (2xVM)- rated ceramic capacitor between the CPH and CPL pins.
CPL	4	4	PWR	

表 6-1. Pin Functions (续)

PIN NAME	36-pin package		TYPE ⁽¹⁾	DESCRIPTION
	DRV8317S	DRV8317H		
CSAREF	33	33	PWR I	Current sense amplifier power supply input/reference. Connect a X5R or X7R, 0.1- μ F, 6.3-V ceramic capacitor between the CSAREF and AGND pins.
GAIN	—	29	I	Available only in hardware variant (DRV8317H). The pin is a 4-level input pin for current sense amplifier gain setting.
INHA	23	23	I	High-side driver control input for OUTA. This pin controls the state of the high-side MOSFET in 6x/3x PWM Mode.
INHB	25	25	I	High-side driver control input for OUTB. This pin controls the state of the high-side MOSFET in 6x/3x PWM Mode.
INHC	27	27	I	High-side driver control input for OUTC. This pin controls the state of the high-side MOSFET in 6x/3x PWM Mode.
INLA	24	24	I	Low-side driver control input for OUTA. This pin controls the state of the low-side MOSFET in 6x PWM Mode.
INLB	26	26	I	Low-side driver control input for OUTB. This pin controls the state of the low-side MOSFET in 6x PWM Mode.
INLC	28	28	I	Low-side driver control input for OUTC. This pin controls the state of the low-side MOSFET in 6x PWM Mode.
MODE	—	31	I	Available only in hardware variant (DRV8317H). This is a 4-level input pin for PWM mode setting.
NC	3	3, 32	—	No connect. Leave the pin floating.
nFAULT	2	2	O	Fault indication pin. Pulled low during fault condition. Open-drain output; requires an external pull-up resistor to AVDD.
nSCS	32	—	I	Available only in SPI variant (DRV8317S). Serial chip select. A logic low on this pin enables serial interface communication.
nSLEEP	1	1	I	When this pin is logic low the device goes to a low-power sleep mode. A 15 to 50- μ s low pulse on nSLEEP pin can be used to reset fault conditions without entering sleep mode.
OUTA	11, 12	11, 12	O	Half-bridge output A. Connect to motor winding.
OUTB	14, 15	14, 15	O	Half-bridge output B. Connect to motor winding.
OUTC	17, 18	17, 18	O	Half-bridge output C. Connect to motor winding.
PGND	10, 13, 16, 19	10, 13, 16, 19	PWR	Device power ground. Connect to a separate ground plane. ²
SCLK	31	—	I	Available only in SPI variant (DRV8317S). Serial clock input. Serial data is shifted out on the rising edge and captured on the falling edge of SCLK.
SDI	30	—	I	Available only in SPI variant (DRV8317S). Serial data input. Data (input) is captured on the falling edge of the SCLK pin (SPI devices).
SDO	29	—	O	Available only in SPI variant (DRV8317S). Serial data output. Data (output) is shifted out on the rising edge of the SCLK pin.
SLEW	—	30	I	Available only in hardware variant (DRV8317H). This pin is a 4-level input pin for OUTx voltage slew rate setting.
SOA	36	36	O	Current sense amplifier output for OUTA.
SOB	35	35	O	Current sense amplifier output for OUTB.
SOC	34	34	O	Current sense amplifier output for OUTC.
VIN_AVDD	7	7	PWR	Input supply for AVDD LDO
VM	8, 9, 20	8, 9, 20	PWR	Device and motor power supply. Connect to motor supply voltage; bypass to PGND with a 0.1- μ F capacitor plus one bulk capacitor. TI recommends a capacitor voltage rating at least twice the normal operating voltage of the device
Thermal pad			PWR	Must be connected to AGND.

(1) I = input, O = output, PWR = power, GND = ground, NC = no connect

7 Specifications

7.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted)⁽¹⁾

	MIN	MAX	UNIT
Power supply pin voltage (VM, VIN_AVDD)	- 0.3	24	V
Power supply voltage ramp during power up (VM)		2	V/μs
Voltage difference between ground pins (PGND, AGND)	- 0.3	0.3	V
Charge pump voltage (CP)	- 0.3	V _M + 6	V
Analog regulator pin voltage (AVDD)	- 0.3	4	V
Logic pin input voltage (INHx, INLx, nSCS, nSLEEP, SCLK, SDI, GAIN, MODE, SLEW)	- 0.3	6	V
Logic pin output voltage (SDO)	- 0.3	6	V
Open drain pin output voltage (nFAULT)	- 0.3	6	V
Open drain output current range (nFAULT)	0	5	mA
Current sense amplifier reference supply input (CSAREF)	-0.3	4	V
Current sense amplifier output (SOx)	-0.3	4	V
Output pin voltage (OUTA, OUTB, OUTC)	- 1	V _M + 1 ⁽²⁾	V
Ambient temperature, T _A	- 40	125	°C
Junction temperature, T _J	- 40	150	°C
Storage temperature, T _{stg}	- 65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime
- (2) Maximum voltage supported on OUTx pin is 24V

7.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500	V
		Charged device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±750	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V _{VM}	Power supply voltage	V _{VM} , V _{VIN_AVDD}	4.5	12	20	V
I _{OUT} ⁽¹⁾	Peak output winding current	V _{VM} ≥ 6 V, OUTA, OUTB, OUTC			5	A
		4.5 V ≤ V _{VM} < 6 V, OUTA, OUTB, OUTC			3	A
V _{OD}	Open drain pullup voltage	nFAULT	- 0.3		5.5	V
I _{OD}	Open drain output current capability	nFAULT			5	mA
T _A	Operating ambient temperature		- 40		125	°C
T _J	Operating Junction temperature		- 40		150	°C

- (1) Power dissipation and thermal limits must be observed

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		DRV8317	UNIT
		REE (WQFN)	
		36	
$R_{\theta JA}$	Junction-to-ambient thermal resistance (JEDEC 4-layer PCB, 6 thermal vias)	36.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	23.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	14	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	14	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	4.1	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLIES						
I_{VMQ}	VM sleep mode current	$V_{VM} = 12\text{ V}$, nSLEEP = 0, $T_A = 25^{\circ}\text{C}$		1.7	3	μA
		nSLEEP = 0, $T_A = 125^{\circ}\text{C}$			10	μA
I_{VMS}	VM standby mode current	$V_{VM} = 12\text{ V}$, nSLEEP = 1, INHx = INLx = 0, SPI = 'OFF', $T_A = 25^{\circ}\text{C}$		8	10	mA
		nSLEEP = 1, INHx = INLx = 0, SPI = 'OFF'		8	10	mA
I_{VM}	VM operating mode current	$V_{VM} = 12\text{ V}$, nSLEEP = 1, $f_{PWM} = 25\text{ kHz}$, $T_A = 25^{\circ}\text{C}$		10	12	mA
		$V_{VM} = 12\text{ V}$, nSLEEP = 1, $f_{PWM} = 200\text{ kHz}$, $T_A = 25^{\circ}\text{C}$		10	14	mA
		nSLEEP = 1, $f_{PWM} = 25\text{ kHz}$		10	12	mA
		nSLEEP = 1, $f_{PWM} = 200\text{ kHz}$		10	15	mA
V_{AVDD}	Analog regulator voltage	$V_{VM} \geq 6\text{V}$, $V_{VIN_AVDD} \geq 6\text{V}$, $0\text{ mA} \leq I_{AVDD} \leq 80\text{ mA}$	3.15	3.3	3.45	V
V_{AVDD}	Analog regulator voltage	$4.5\text{V} \leq V_{VM} < 6\text{V}$, $4.5\text{V} \leq V_{VIN_AVDD} < 6\text{V}$, $0\text{ mA} \leq I_{AVDD} \leq 80\text{ mA}$	3.15	3.3	3.45	V
I_{AVDD}	Analog regulator external load	$4.5\text{V} \leq V_{VM} < 6\text{V}$, $4.5\text{V} \leq V_{VIN_AVDD} < 6\text{V}$			80	mA
I_{AVDD}	Analog regulator external load	$V_{VM} \geq 6\text{V}$, $V_{VIN_AVDD} \geq 6\text{V}$			80	mA
I_{AVDD_LIM}	Analog regulator current limit	$V_{AVDD} \geq 2.7\text{V}$, soft short to GND	100	125	150	mA
C_{AVDD}	Capacitance for AVDD	External load $I_{AVDD} = 0\text{ mA}$	0.5	2.2	7.05	μF
		External load $0\text{ mA} \leq I_{AVDD} \leq 80\text{ mA}$	2.35	4.7	7.05	μF
V_{CP}	Charge pump regulator voltage	$4.5\text{V} \leq V_{VM} < 6\text{V}$, CP with respect to VM	3	5	5.5	V
V_{CP}	Charge pump regulator voltage	$V_{VM} \geq 6\text{V}$, CP with respect to VM	4.5	5	5.5	V
t_{WAKE}	Wakeup time	$V_{VM} > V_{UVLO}$, nSLEEP = 1 to output ready		1	3	ms
t_{WAKE_CSA}	Wakeup time for CSA	$V_{CSAREF} > V_{CSAREF_UV}$ to SOx ready, when nSLEEP = 1		30		μs
t_{SLEEP}	Turn-off time	nSLEEP = 0 to driver tri-stated		100	200	μs
t_{RST}	Reset Pulse time	nSLEEP = 0 period to reset faults	15		50	μs
FOUR-LEVEL INPUTS (GAIN, MODE, SLEW)						

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{L1}	Input mode 1 voltage	Tied to AGND	0		$0.2 \cdot AV_{DD}$	V
V_{L2}	Input mode 2 voltage	$47\text{ k}\Omega \pm 5\%$ tied to AGND	$0.27 \cdot AV_{DD}$	$0.4 \cdot AV_{DD}$	$0.545 \cdot AV_{DD}$	V
V_{L3}	Input mode 3 voltage	Hi-Z	$0.606 \cdot AV_{DD}$	$0.757 \cdot AV_{DD}$	$0.909 \cdot AV_{DD}$	V
V_{L4}	Input mode 4 voltage	Tied to AVDD	$0.94 \cdot AV_{DD}$		AVDD	V
R_{PU}	Input pullup resistance	To AVDD		48		$\text{k}\Omega$
R_{PD}	Input pulldown resistance	To AGND		160		$\text{k}\Omega$
DRIVER OUTPUTS						
$R_{DS(ON)}$	Total MOSFET on resistance (High-side + Low-side)	$V_{VM} \geq 6\text{ V}$, $I_{OUT} = 1\text{ A}$, $T_J = 25^{\circ}\text{C}$, includes bond wire and metallization resistance		130	157	$\text{m}\Omega$
		$V_{VM} \geq 6\text{ V}$, $I_{OUT} = 1\text{ A}$, $T_J = 125^{\circ}\text{C}$, across process, includes bond wire and metallization resistance		180	221.5	$\text{m}\Omega$
$R_{DS(ON)}$	Total MOSFET on resistance (High-side + Low-side)	$4.5\text{ V} \leq V_{VM} < 6\text{ V}$, $I_{OUT} = 1\text{ A}$, $T_J = 25^{\circ}\text{C}$, includes bond wire and metallization resistance		155	210	$\text{m}\Omega$
		$4.5\text{ V} \leq V_{VM} < 6\text{ V}$, $I_{OUT} = 1\text{ A}$, $T_J = 125^{\circ}\text{C}$, across process, includes bond wire and metallization resistance		225	290	$\text{m}\Omega$
SR_RISE	Phase pin slew rate switching low to high (Rising from 20 % to 80 % of VM)	$V_{VM} = 12\text{ V}$, SLEW_RATE = 00b (SPI Variant) or SLEW pin tied to AGND (HW Variant)	13.75	25	36.25	$\text{V}/\mu\text{s}$
		$V_{VM} = 12\text{ V}$, SLEW_RATE = 01b (SPI Variant) or SLEW pin to $47\text{ k}\Omega$ +/- 5% tied to AGND (HW Variant)	27.5	50	72.5	$\text{V}/\mu\text{s}$
		$V_{VM} = 12\text{ V}$, SLEW_RATE = 10b (SPI Variant) or SLEW pin to Hi-Z (HW Variant)	62.5	125	187.5	$\text{V}/\mu\text{s}$
		$V_{VM} = 12\text{ V}$, SLEW_RATE = 11b (SPI Variant) or SLEW pin tied to AVDD (HW Variant)	80	200	320	$\text{V}/\mu\text{s}$
SR_FALL	Phase pin slew rate switching high to low (Falling from 80 % to 20 % of VM)	$V_{VM} = 12\text{ V}$, SLEW_RATE = 00b (SPI Variant) or SLEW pin tied to AGND (HW Variant)	13.75	25	48	$\text{V}/\mu\text{s}$
		$V_{VM} = 12\text{ V}$, SLEW_RATE = 01b (SPI Variant) or SLEW pin to $47\text{ k}\Omega$ +/- 5% tied to AGND (HW Variant)	27.5	50	72.5	$\text{V}/\mu\text{s}$
		$V_{VM} = 12\text{ V}$, SLEW_RATE = 10b (SPI Variant) or SLEW pin to Hi-Z (HW Variant)	62.5	125	187.5	$\text{V}/\mu\text{s}$
		$V_{VM} = 12\text{ V}$, SLEW_RATE = 11b (SPI Variant) or SLEW pin tied to AVDD (HW Variant)	80	200	320	$\text{V}/\mu\text{s}$
I_{LEAK}	Leakage current OUTx	$V_{VM} = V_{OUTx} = 20\text{ V}$, Standby State		0.7	2	mA
I_{LEAK}	Leakage current OUTx	$V_{OUTx} = 0\text{ V}$, Standby State	-50	-10		μA

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{DEAD}	Dead time (high to low / low to high)	$V_{VM} = 12\text{V}$, SLEW_RATE = 00b (SPI Variant) or SLEW pin tied to AGND (HW Variant)		575	1500	ns
		$V_{VM} = 12\text{V}$, SLEW_RATE = 01b (SPI Variant) or SLEW pin to $47\text{ k}\Omega$ +/- 5% tied to AGND (HW Variant)		325	750	ns
		$V_{VM} = 12\text{V}$, SLEW_RATE = 10b (SPI Variant) or SLEW pin to Hi-Z (HW Variant)		250	600	ns
		$V_{VM} = 12\text{V}$, SLEW_RATE = 11b (SPI Variant) or SLEW pin tied to AVDD (HW Variant)		250	600	ns
t_{PD}	Propagation delay (high-side / low-side ON/OFF)	INHx = 1 to OUTx transision, $V_{VM} = 12\text{V}$, SLEW = 00b (SPI Variant) or SLEW pin tied to AGND (HW Variant)		1300	1750	ns
		INHx = 1 to OUTx transision, $V_{VM} = 12\text{V}$, SLEW = 01b (SPI Variant) or SLEW pin to $47\text{ k}\Omega$ +/- 5% tied to AGND (HW Variant)		800	1050	ns
		INHx = 1 to OUTx transision, $V_{VM} = 12\text{V}$, SLEW = 10b (SPI Variant) or SLEW pin to Hi-Z (HW Variant)		450	600	ns
		INHx = 1 to OUTx transision, $V_{VM} = 12\text{V}$, SLEW = 11b (SPI Variant) or SLEW pin tied to AVDD (HW Variant)		425	500	ns
$t_{\text{MIN_PULSE}}$	Minimum output pulse width	SLEW = 11b (SPI Variant) or SLEW pin tied to AVDD (HW Variant)	500			ns
CURRENT SENSE AMPLIFIER						
G_{CSA}	Current sense gain	CSA_GAIN = 00b (SPI Variant) or GAIN pin tied to AGND (HW Variant)		0.25		V/A
		CSA_GAIN = 01b (SPI Variant) or GAIN pin to $47\text{ k}\Omega$ +/- 5% tied to AGND (HW Variant)		0.5		V/A
		CSA_GAIN = 10b (SPI Variant) or GAIN pin to Hi-Z (HW Variant)		1		V/A
		CSA_GAIN = 11b (SPI Variant) or GAIN pin tied to AVDD (HW Variant)		2		V/A
$G_{\text{CSA_ERR}}$	Current sense gain error	$T_A = 25^{\circ}\text{C}$, $I_{\text{PHASE}} \leq 2.5\text{ A}$	-3		3	%
$G_{\text{CSA_ERR}}$	Current sense gain error	$T_A = 25^{\circ}\text{C}$, $2.5\text{ A} < I_{\text{PHASE}} \leq 4\text{ A}$	-3.5		3.5	%
$G_{\text{CSA_ERR}}$	Current sense gain error	$T_A = 25^{\circ}\text{C}$, $4\text{ A} < I_{\text{PHASE}} \leq 5\text{ A}$	-3.5		4.5	%
$G_{\text{CSA_ERR}}$	Current sense gain error	$I_{\text{PHASE}} \leq 2.5\text{ A}$	-4.5		4.5	%
$G_{\text{CSA_ERR}}$	Current sense gain error	$2.5\text{ A} < I_{\text{PHASE}} \leq 4\text{ A}$	-5		6	%
$G_{\text{CSA_ERR}}$	Current sense gain error	$4\text{ A} < I_{\text{PHASE}} \leq 5\text{ A}$	-5		8	%
I_{MATCH}	Current sense gain error matching between phases A, B and C	$T_J = 25^{\circ}\text{C}$	-3		3	%
			-5		5	%
FSPOS	Full scale positive current measurement		5			A
FSNEG	Full scale negative current measurement				-5	A
V_{LINEAR}	SOX output voltage linear range		0.25		$V_{\text{REF}} - 0.25$	V

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{\text{OFFSET_RT}}$	Current sense offset low side current input (Room Temperature)	$T_J = 25^{\circ}\text{C}$, Phase current = 0 A, $G_{\text{CSA}} = 0.25\text{ V/A}$	- 100		100	mA
		$T_J = 25^{\circ}\text{C}$, Phase current = 0 A, $G_{\text{CSA}} = 0.5\text{ V/A}$	- 50		50	mA
		$T_J = 25^{\circ}\text{C}$, Phase current = 0 A, $G_{\text{CSA}} = 1\text{ V/A}$	- 30		30	mA
		$T_J = 25^{\circ}\text{C}$, Phase current = 0 A, $G_{\text{CSA}} = 2\text{ V/A}$	- 30		30	mA
I_{OFFSET}	Current sense offset low side current input	Phase current = 0 A, $G_{\text{CSA}} = 0.25\text{ V/A}$	- 140		140	mA
		Phase current = 0 A, $G_{\text{CSA}} = 0.5\text{ V/A}$	- 70		70	mA
		Phase current = 0 A, $G_{\text{CSA}} = 1\text{ V/A}$	- 50		50	mA
		Phase current = 0 A, $G_{\text{CSA}} = 2\text{ V/A}$	- 50		50	mA
t_{SET}	Settling time to $\pm 1\%$, 30 pF	Step on SOX = 1.2 V, $G_{\text{CSA}} = 0.25\text{ V/A}$			1	$\mu\text{ s}$
		Step on SOX = 1.2 V, $G_{\text{CSA}} = 0.5\text{ V/A}$			1	$\mu\text{ s}$
		Step on SOX = 1.2 V, $G_{\text{CSA}} = 1\text{ V/A}$			1	$\mu\text{ s}$
		Step on SOX = 1.2 V, $G_{\text{CSA}} = 2\text{ V/A}$			1	$\mu\text{ s}$
V_{DRIFT}	Drift offset	Phase current = 0 A	- 360		360	$\mu\text{A}/^{\circ}\text{C}$
I_{CSAREF}	CSAREF input current	$V_{\text{REF}} = 3.0\text{ V}$		12	20	μA

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
PROTECTION CIRCUITS						
V_{OVP}	Supply overvoltage protection (OVP)	VM rising	21	22	23	V
		VM falling	20	21	22	V
V_{OVP_HYS}	Supply overvoltage protection hysteresis	Falling to rising threshold	900	1000	1200	mV
t_{OVP}	Supply overvoltage protection deglitch time		3	5	7	μs
V_{UVLO}	Supply undervoltage lockout (UVLO)	VM rising	4.25	4.4	4.61	V
		VM falling	4.1	4.2	4.35	V
V_{UVLO_HYS}	Supply undervoltage lockout hysteresis	Rising to falling threshold	140	210	350	mV
t_{UVLO}	Supply undervoltage lockout deglitch time		3	5	7	μs
$V_{VMUV_WARN_RISE}$	Supply (VM) undervoltage warning, rising	VM rising, VMUV_WARN_RISE = 0000b	5.4	5.62	6	V
		VM rising, VMUV_WARN_RISE = 0001b	6	6.25	6.6	V
		VM rising, VMUV_WARN_RISE = 0010b	6.6	6.87	7.25	V
		VM rising, VMUV_WARN_RISE = 0011b	7.15	7.5	7.95	V
		VM rising, VMUV_WARN_RISE = 0100b	7.8	8.12	8.6	V
		VM rising, VMUV_WARN_RISE = 0101b	8.4	8.75	9.3	V
		VM rising, VMUV_WARN_RISE = 0110b	9	9.37	9.9	V
		VM rising, VMUV_WARN_RISE = 0111b	9.6	10	10.6	V
		VM rising, VMUV_WARN_RISE = 1000b	10.2	10.62	11.2	V
		VM rising, VMUV_WARN_RISE = 1001b	10.8	11.25	11.9	V
		VM rising, VMUV_WARN_RISE = 1010b	11.35	11.87	12.55	V
		VM rising, VMUV_WARN_RISE = 1011b	11.95	12.5	13.15	V
		VM rising, VMUV_WARN_RISE = 1100b	13.2	13.75	14.5	V
		VM rising, VMUV_WARN_RISE = 1101b	14.3	15.00	15.9	V
		VM rising, VMUV_WARN_RISE = 1110b	15.5	16.25	17.1	V
VM rising, VMUV_WARN_RISE = 1111b	16.7	17.5	18.6	V		

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{VMUV_WARN_FALL}$	Supply (VM) undervoltage warning, falling	VM falling, VMUV_WARN_FALL = 0000b	5.1	5.4	5.75	V
		VM falling, VMUV_WARN_FALL = 0001b	5.7	6.0	6.3	V
		VM falling, VMUV_WARN_FALL = 0010b	6.25	6.6	6.95	V
		VM falling, VMUV_WARN_FALL = 0011b	6.8	7.2	7.6	V
		VM falling, VMUV_WARN_FALL = 0100b	7.4	7.8	8.2	V
		VM falling, VMUV_WARN_FALL = 0101b	7.95	8.4	8.85	V
		VM falling, VMUV_WARN_FALL = 0110b	8.5	9.0	9.5	V
		VM falling, VMUV_WARN_FALL = 0111b	9.05	9.6	10.15	V
		VM falling, VMUV_WARN_FALL = 1000b	9.7	10.2	10.7	V
		VM falling, VMUV_WARN_FALL = 1001b	10.15	10.8	11.4	V
		VM falling, VMUV_WARN_FALL = 1010b	10.75	11.4	12	V
		VM falling, VMUV_WARN_FALL = 1011b	11.3	12.0	12.6	V
		VM falling, VMUV_WARN_FALL = 1100b	12.5	13.2	13.8	V
		VM falling, VMUV_WARN_FALL = 1101b	13.5	14.4	15.3	V
		VM falling, VMUV_WARN_FALL = 1110b	14.7	15.6	16.4	V
VM falling, VMUV_WARN_FALL = 1111b	15.9	16.8	17.8	V		
$t_{VMUV_WARN_DG}$	Supply undervoltage warning deglitch time	VMUV_TDG = 00b	0.1	0.3	0.45	μs
		VMUV_TDG = 01b	0.35	0.6	0.8	μs
		VMUV_TDG = 10b	0.55	0.9	1.35	μs
		VMUV_TDG = 11b	1.4	2	2.5	μs
$t_{VMUV_WARN_DG}$	Supply undervoltage warning deglitch time (HW variant)		0.35	0.6	0.8	μs
$V_{VIN_AVDD_UV}$	AVDD supply input undervoltage lockout (VIN_AVDD_UV)	VIN_AVDD rising	4.25	4.4	4.61	V
		VIN_AVDD falling	4.1	4.2	4.35	V
$V_{VIN_AVDD_UV_HYS}$	Supply undervoltage lockout hysteresis	Rising to falling threshold	140	210	350	mV
V_{CPUV}	Charge pump undervoltage lockout (above VM)	Supply rising	2.64	2.8	2.95	V
		Supply falling	2.35	2.6	2.7	V
V_{CPUV_HYS}	Charge pump undervoltage lockout hysteresis	Rising to falling threshold	160	210	245	mV
t_{CPUV}	Charge pump undervoltage lockout deglitch time		3	5	7	μs
V_{AVDD_UV}	Analog regulator undervoltage lockout	Supply rising	2.7	2.8	2.9	V
		Supply falling	2.6	2.7	2.8	V
$V_{AVDD_UV_HYS}$	Analog regulator undervoltage lockout hysteresis	Rising to falling threshold	80	100	150	mV
I_{OCP}	Overcurrent protection trip point		6	9.5	12	A
$t_{BLANK}^{(1)}$	Overcurrent protection blanking time	OCP_TBLANK = 00b	0.15	0.3	0.45	μs
		OCP_TBLANK = 01b	0.45	0.7	0.85	μs
		OCP_TBLANK = 10b	0.7	1	1.25	μs
		OCP_TBLANK = 10b	0.9	1.2	1.5	μs

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{\text{BLANK}}^{(1)}$	Overcurrent protection blanking time (HW Variant)		0.45	0.7	0.85	μs
$t_{\text{OCP}}^{(1)}$	Overcurrent protection deglitch time	OCP_DEG = 00b	0.1	0.3	0.45	μs
		OCP_DEG = 01b	0.35	0.6	0.85	μs
		OCP_DEG = 10b	0.6	0.9	1.25	μs
		OCP_DEG = 11b	0.8	1.2	1.5	μs
$t_{\text{OCP}}^{(1)}$	Overcurrent protection deglitch time (HW Variant)		0.35	0.6	0.85	μs
t_{RETRY}	Overcurrent protection retry time	FAST_TRETRY = 00b	0.35	0.5	0.7	ms
		FAST_TRETRY = 01b	0.75	1	1.3	ms
		FAST_TRETRY = 10b	1.65	2	2.45	ms
		FAST_TRETRY = 11b	4.35	5	5.85	ms
t_{RETRY}	Overcurrent protection retry time	SLOW_TRETRY = 00b	350	500	700	ms
		SLOW_TRETRY = 01b	750	1000	1300	ms
		SLOW_TRETRY = 10b	1650	2000	2450	ms
		SLOW_TRETRY = 11b	4350	5000	5850	ms
t_{RETRY}	Overcurrent protection retry time (HW Variant)		4.35	5	5.85	ms
$T_{\text{OTW_FET}}$	Overtemperature warning threshold (FET)	Die temperature (T_J) Rising	110	125	140	$^{\circ}\text{C}$
$T_{\text{OTW_HYS_FET}}$	Overtemperature warning hysteresis (FET)	Die temperature (T_J)	15	20	25	$^{\circ}\text{C}$
$T_{\text{OTS_FET}}$	Overtemperature shutdown threshold (FET)	Die temperature (T_J) Rising	145	160	175	$^{\circ}\text{C}$
$T_{\text{OTS_HYS_FET}}$	Overtemperature shutdown hysteresis (FET)	Die temperature (T_J)	14	20	25	$^{\circ}\text{C}$
$T_{\text{OTS_LDO}}$	Overtemperature shutdown threshold (LDO)	Die temperature (T_J) Rising	145	160	175	$^{\circ}\text{C}$
$T_{\text{OTS_HYS_LDO}}$	Overtemperature shutdown hysteresis (LDO)	Die temperature (T_J)	14	20	25	$^{\circ}\text{C}$
LOGIC-LEVEL INPUTS (INHx, INLx, nSLEEP, SCLK, SDI)						
V_{IL}	Input logic low voltage	nSLEEP	0		0.7	V
V_{IL}	Input logic low voltage	SDI, INLx, INHx, SCLK	0		0.65	V
V_{IH}	Input logic high voltage	nSLEEP	1.7		5.5	V
V_{IH}	Input logic high voltage	SDI, INLx, INHx, SCLK	1.5		3.6	V
V_{HYS}	Input logic hysteresis	nSLEEP	200		600	mV
V_{HYS}	Input logic hysteresis	SDI, INLx, INHx, SCLK	200		500	mV
I_{IL}	Input logic low current	nSLEEP, SDI, INLx, INHx, SCLK (Pin Voltage) = 0 V	- 1		1	μA
		nSLEEP (Pin Voltage) = 5V			40	μA
I_{IH}	Input logic high current	Other pins, $3\text{ V} \leq V_{\text{PIN}}$ (Pin Voltage) $\leq 3.6\text{ V}$			30	μA
R_{PD}	Input pulldown resistance	nSLEEP		150	300	$\text{k}\Omega$
		SDI, SCLK, INHx, INLx		150	300	$\text{k}\Omega$
C_{ID}	Input capacitance	nSLEEP, SDI, SCLK, INHx, INLx		30		pF
LOGIC-LEVEL INPUTS (nSCS)						
V_{IL}	Input logic low voltage		0		0.7	V
V_{IH}	Input logic high voltage		1.5		3.6	V

$T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VM} = 4.5$ to 20 V (unless otherwise noted). Typical limits apply for $T_A = 25^{\circ}\text{C}$, $V_{VM} = 12\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{HYS}	Input logic hysteresis		200		500	mV
I_{IL}	Input logic low current	V_{PIN} (Pin Voltage) = 0 V			95	μA
I_{IH}	Input logic high current	$3\text{V} \leq V_{PIN}$ (Pin Voltage) $\leq 3.6\text{V}$	-1		1	μA
R_{PU}	Input pullup resistance		35	48	75	$\text{k}\Omega$
C_{ID}	Input capacitance			30		pF
OPEN-DRAIN OUTPUTS (nFAULT)						
V_{OL}	Output logic low voltage	$I_{OD} = -5\text{ mA}$			0.4	V
I_{OH}	Output logic high current	$3\text{V} \leq V_{OD} \leq 3.6\text{ V}$	-1		1	μA
C_{OD}	Output capacitance			30		pF
PUSH-PULL OUTPUTS (SDO)						
V_{OL}	Output logic low voltage	$I_{OP} = -5\text{ mA}$, $3\text{V} \leq V_{AVDD} \leq 3.6\text{V}$	0		0.5	V
V_{OH}	Output logic high voltage	$I_{OP} = 5\text{ mA}$, $3\text{V} \leq V_{AVDD} \leq 3.6\text{V}$	$V_{AVDD} - 0.5$		3.6	V
I_{OL}	Output logic low current	$V_{OP} = 0\text{ V}$	-1		1	μA
I_{OH}	Output logic high current	$V_{OP} = 5\text{ V}$	-2		2	μA
C_{OD}	Output capacitance			30		pF

(1) $(t_{OCP} + t_{BLANK})$ must not exceed $2.2\ \mu\text{s}$

8 Detailed Description

8.1 Overview

The DRV8317 is an integrated MOSFET driver for 3-phase motor-drive applications. The combined high-side and low-side FETs' on-state resistance is 130-m Ω (typical). The device reduces system component count, cost, and complexity by integrating three MOSFET half-bridges, gate drivers, charge pump, current sense amplifiers and linear regulator for external loads. In DRV8317S, a standard serial peripheral interface (SPI) provides a simple method for configuring the various device settings and reading fault status information through an external controller. In DRV8317H, a hardware (pin-based) interface allows configuring the PWM mode (6x or 3x), current sense amplifier gain and output slew rate through pin voltage levels.

The gate driver architecture is designed to protect against short-circuit events and dV/dt parasitic turn-on of the internal power MOSFETs.

The DRV8317 integrates three bi-directional low-side current sense amplifiers for monitoring the current through each of the half-bridges using a built-in current sense circuit; no external current sense resistors are needed. The gain of the current sense amplifiers can be adjusted through the SPI or hardware interface.

In addition to the high level of device integration, the DRV8317 provides a wide range of integrated protection features. These features include power supply undervoltage lockout (UVLO), over voltage protection (OVP), charge pump undervoltage lockout (CPUV), over current protection (OCP), AVDD under voltage lockout (AVDD_UV) and over temperature warning and shutdown (OTW and OTS). Fault events are indicated by the nFAULT pin with detailed information available in the status registers in the SPI variant.

The DRV8317S, DRV8317H devices are available in 0.4-mm pin pitch, WQFN surface-mount packages. The WQFN package size is 5.00-mm \times 4.00-mm with a height of 0.8-mm.

8.2 Functional Block Diagram

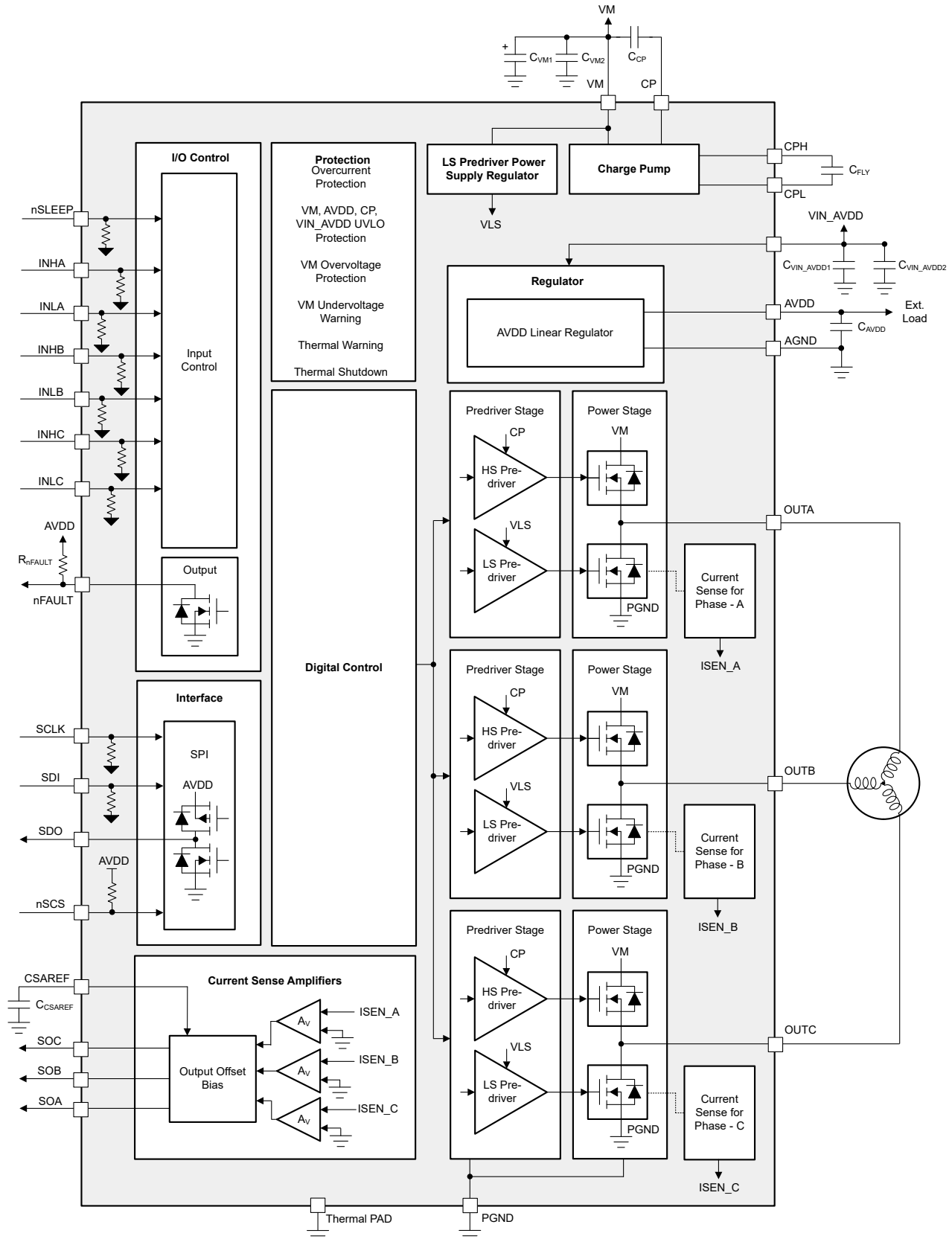


图 6-1. DRV8317S Functional Block Diagram

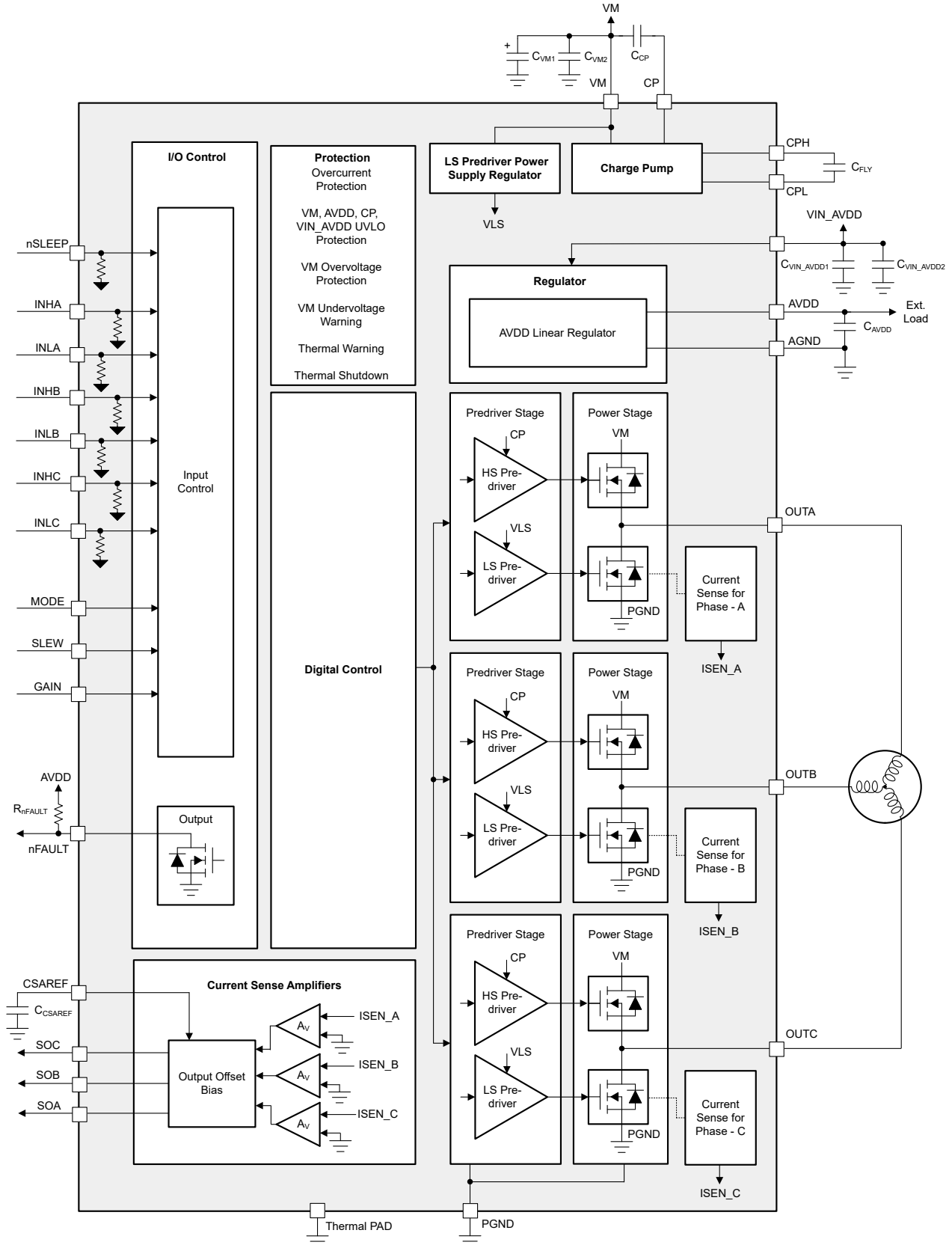


图 8-2. DRV8317H Functional Block Diagram

8.3 Feature Description

表 8-1 lists the recommended values of the external components for the driver.

表 8-1. DRV8317 External Components

COMPONENTS	PIN 1	PIN 2	RECOMMENDED
C _{VM1}	VM	PGND	X5R or X7R, 0.1-μF, (2 x VM)-rated capacitor
C _{VM2}	VM	PGND	≥ 10-μF, (2 x VM)-rated electrolytic capacitor
C _{VIN_AVDD1}	VIN_AVDD	AGND	X5R or X7R, 0.1-μF, (2 x VIN_AVDD)-rated capacitor
C _{VIN_AVDD2}	VIN_AVDD	AGND	≥ 10-μF, (2 x VIN_AVDD)-rated capacitor
C _{FLY}	CPH	CPL	X5R or X7R, 0.1-μF, (2 x VM)-rated capacitor
C _{CP}	CP	VM	X5R or X7R, 16-V, 1-μF capacitor
C _{AVDD}	AVDD	AGND	X5R or X7R, 2.2-μF (no external load) 4.7-μF (up to 80mA load), 6.3-V capacitor
R _{nFAULT}	AVDD	nFAULT	5.1-kΩ, Pull-up resistor
R _{MODE}	MODE	AGND	节 8.3.3.2
R _{SLEW}	SLEW	AGND	节 8.3.3.2
R _{GAIN}	GAIN	AGND	节 8.3.3.2
C _{CSAREF}	CSAREF	AGND	X5R or X7R, 0.1-μF, (2 x CSAREF)-rated capacitor

8.3.1 Output Stage

The DRV8317 consists of integrated N-channel FETs (high-side and low-side) connected in a three-phase bridge configuration. A doubler charge pump provides the proper gate-bias voltage to the high-side N-channel FETs across a wide operating (VM) voltage range in addition to providing 100% duty-cycle support. An internal linear regulator operating from the VM supply provides the gate-bias voltage (VLS) for the low-side N-channel FETs.

8.3.2 Control Modes

The DRV8317 family of devices provides three different control modes to support various commutation and control methods. 表 8-2 shows the various modes of the DRV8317 device.

表 8-2. PWM Control Modes

PWM Control Mode	PWM_MODE register (DRV8317S)	MODE Pin (DRV8317H)
6x PWM	PWM_MODE = 00b	MODE pin tied to AGND directly or tied to AGND via 47-kΩ resistor
6x direct PWM	PWM_MODE = 01b	Not Available
3x PWM	PWM_MODE = 10b	MODE pin floating (Hi-Z) or tied to AVDD
3x direct PWM	PWM_MODE = 11b	Not Available

The difference between 6x PWM (or 3x PWM) and 6x direct PWM (or 3x direct PWM) is that in the direct (6x or 3x) PWM mode, the delay compensation logic circuit is bypassed and the inputs at INHx, INLx are directly passed on to the gate driver circuit. In the gate driver circuit, a dead time (t_{DRV_DEAD}) is added before driving the FETs to prevent shoot through faults - this dead time is available in all the four PWM control modes.

备注

TI does not recommend changing the MODE pin or PWM_MODE register during power up of the device (during t_{WAKE}). The MODE pin setting on DRV8317H is latched at power up, so set nSLEEP = 0 before changing the MODE pin configuration on the DRV8317H. In DRV8317S, set all INHx and INLx pins to logic low before changing the PWM_MODE register.

8.3.2.1 6x PWM Mode

In 6x PWM mode, each half-bridge supports three output states: low, high, or high-impedance (Hi-Z). To configure DRV8317H in 6x PWM mode, connect the MODE pin to AGND or connect the MODE pin to AGND via 47-kΩ resistor. To enable 6x PWM mode in DRV8317S, configure the MODE bits with PWM_MODE = 00b or 01b. The corresponding INHx and INLx signals control the output state as listed in 表 8-3.

表 8-3. 6x PWM Mode Truth Table

INHx	INLx	OUTx
0	0	Hi-Z
0	1	L
1	0	H
1	1	Hi-Z

图 8-3 shows the application diagram of DRV8317 configured in 6x PWM mode.

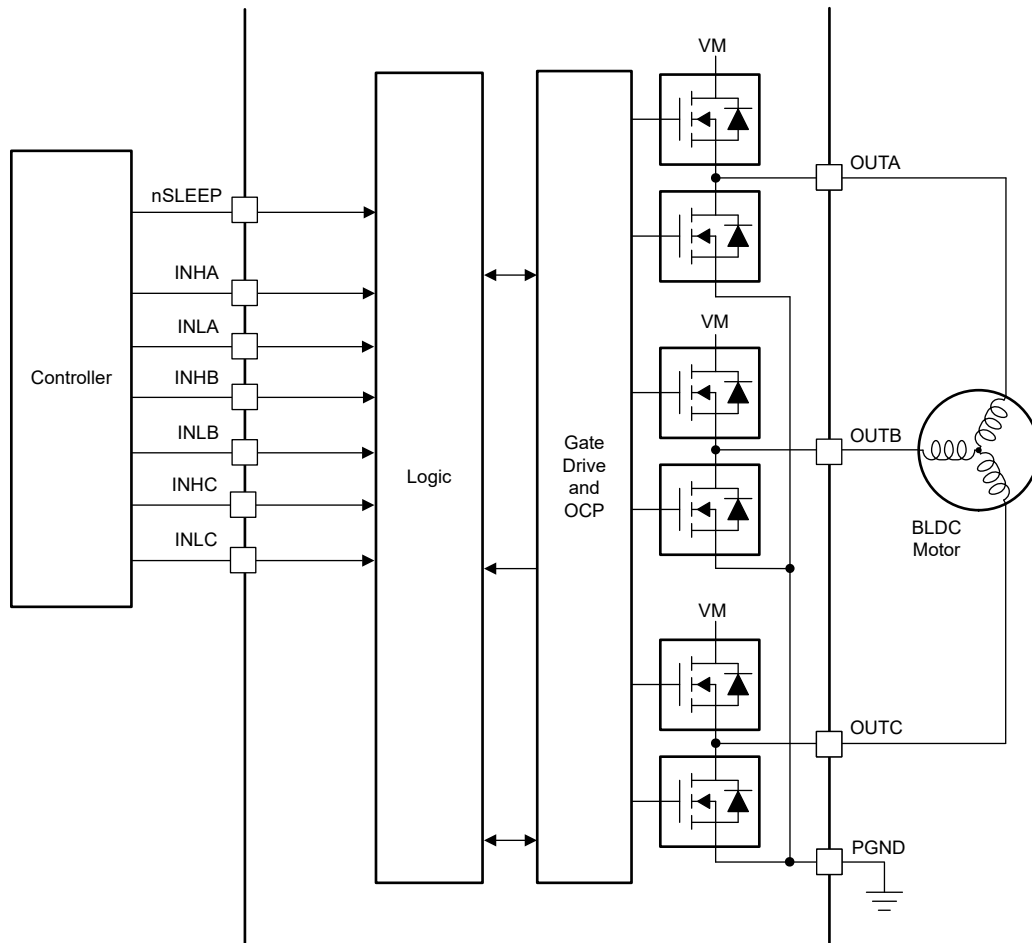


图 8-3. 6x PWM Mode

8.3.2.2 3x PWM Mode

In 3x PWM mode, the INHx pin controls each half-bridge and supports two output states: low or high. To configure DRV8317H in 3x PWM mode, connect the MODE pin to AVDD or keep the MODE pin floating (Hi-Z). To enable 3x PWM mode in DRV8317S, set PWM_MODE to 10b or 11b. The INLx pin is used to put the half bridge in the Hi-Z state. If the Hi-Z state is not required, tie all INLx pins to logic high (for example, by tying them to AVDD). The corresponding INHx and INLx signals control the output state as listed in [表 8-4](#).

表 8-4. 3x PWM Mode Truth Table

INLx	INHx	OUTx
0	X	Hi-Z
1	0	L
1	1	H

图 8-4 shows the typical application diagram of the DRV8317 configured in 3x PWM mode.

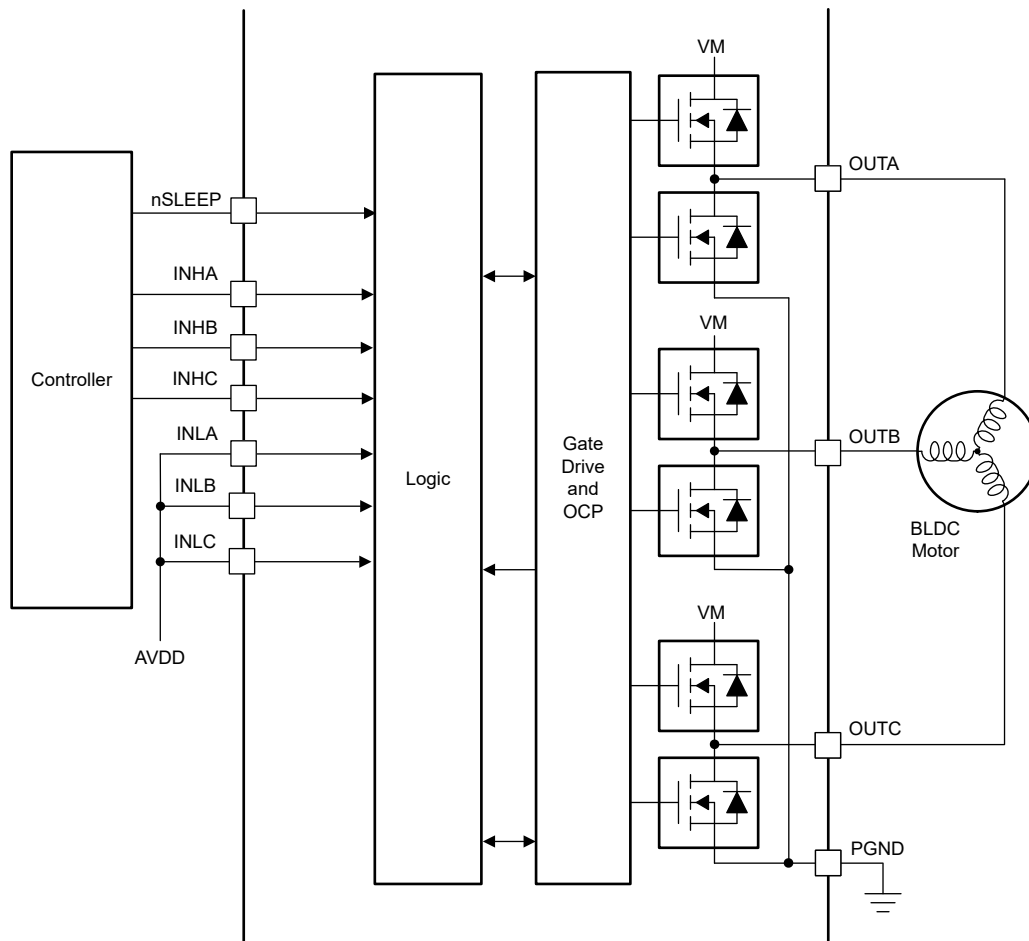


图 8-4. 3x PWM Mode

8.3.3 Device Interface Modes

The DRV8317 family of devices supports two different interface modes (SPI and hardware) to offer either increased simplicity (hardware interface) or greater flexibility (SPI interface). The SPI (DRV8317S) and hardware (DRV8317H) interface modes share the same four pins, allowing the different versions to be pin-to-pin

compatible. Designers are encouraged to evaluate with the SPI interface version due to ease of changing settings, and may consider switching to the hardware interface with minimal modifications to the design.

8.3.3.1 Serial Peripheral Interface (SPI)

The SPI variant (DRV8317S) supports a serial communication bus that allows an external controller to send and receive data with DRV8317. This enables the external controller to configure device settings and read detailed fault information. The interface is a four wire interface using the SCLK, SDI, SDO, and nSCS pins which are described as follows:

- The SCLK (serial clock) pin is an input that accepts a clock signal to determine when data is captured and propagated on the SDI and SDO pins.
- The SDI (serial data in) pin is the data input.
- The SDO (serial data out) pin is the data output.
- The nSCS (serial chip select) pin is the chip select input. A logic low signal on this pin enables SPI communication with the DRV8317.

For more information on the SPI, see [节 8.5](#).

8.3.3.2 Hardware Interface

The hardware variant (DRV8317H) replaces the four SPI pins with three resistor-configurable pins, namely, GAIN, SLEW and MODE (one of the four SPI pins is NC in hardware variant).

PWM control mode, CSA gain and driver output slew rate can be adjusted on the hardware interface by tying the respective pins to AGND, AVDD, pulling down to AGND with a 47-kΩ resistor or by leaving the pin floating (Hi-Z). In DRV8317H, fault conditions are reported on the nFAULT pin, but detailed fault information is not available.

- The GAIN pin configures the gain of the current sense amplifier.
- The SLEW pin configures the slew rate of the output voltage to motor.
- The MODE pin configures the PWM control mode.

For more information on the hardware interface, see [节 8.3.9](#).

表 8-5. Hardware Pins Decode

Configuration	GAIN	SLEW	MODE
Pin tied to AGND	0.25-V/A	25-V/μs	6x PWM mode
Pin pulled to AGND via 47-kΩ	0.5-V/A	50-V/μs	6x PWM mode
Pin floating (Hi-Z)	1-V/A	125-V/μs	3x PWM mode
Pin tied to AVDD	2-V/A	200-V/μs	3x PWM mode

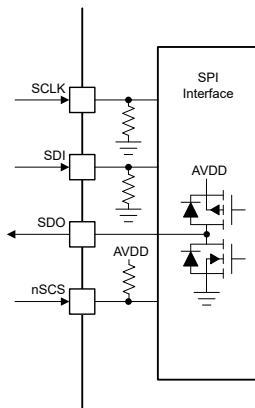


图 8-5. DRV8317S SPI Interface

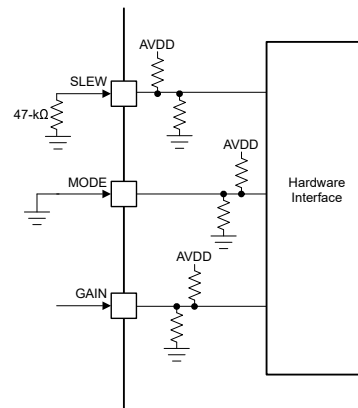


图 8-6. DRV8317H Hardware Interface

8.3.4 AVDD Linear Voltage Regulator

A 3.3-V, 80mA linear regulator is integrated in the DRV8317 and is available to power external circuits. The AVDD regulator is used for powering up the internal circuits of DRV8317 and can also provide power to external circuits like MCU, logic, hall sensors, LEDs for up to 80 mA. The output of the AVDD regulator should be bypassed near the AVDD pin with a X5R or X7R, up to 7.05µF (4.7µF typical), 6.3-V ceramic capacitor routed directly back to the adjacent AGND ground pin.

The AVDD nominal, no-load output voltage is 3.3 V.

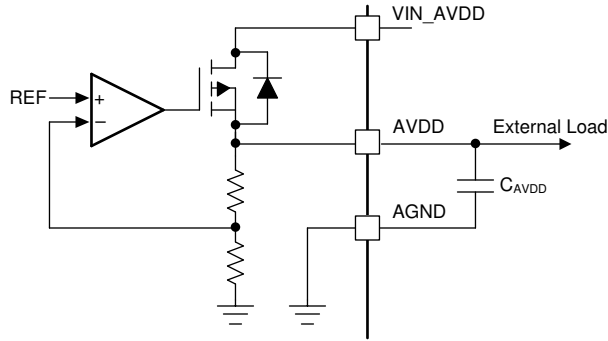


图 8-7. AVDD Linear Regulator Block Diagram

Use 方程式 1 to calculate the power dissipated in the device by the AVDD linear regulator.

$$P = (V_{VIN_AVDD} - V_{AVDD}) \times I_{AVDD} \quad (1)$$

The supply input voltage for AVDD regulator (V_{IN_AVDD}) can be same as VM supply voltage, or lower or higher than VM supply voltage.

8.3.5 Charge Pump

The DRV8317 requires a gate-drive voltage higher than the VM power supply to enhance the high-side FETs fully because the output stages uses N-channel FETs for both high-side and low-side. The DRV8317 integrates a charge pump circuit that generates a voltage above the VM supply for this purpose.

The charge pump requires two external capacitors for operation. See 表 8-1 for details on the capacitor value.

The charge pump shuts down when nSLEEP is low.

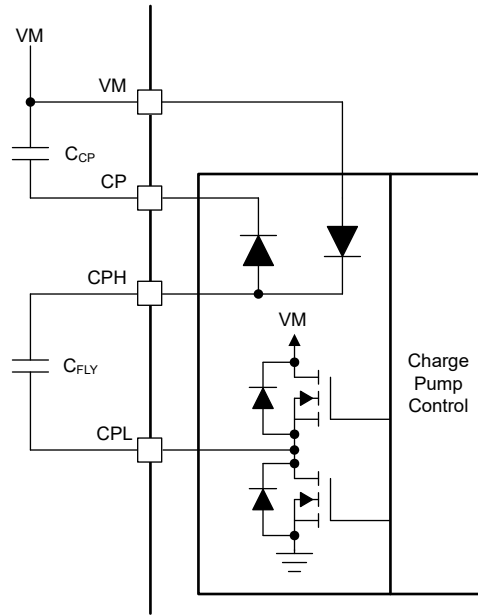


图 8-8. DRV8317 Charge Pump

8.3.6 Slew Rate Control

An adjustable gate-drive current to the MOSFETs allows for driver output slew rate control. The MOSFET VDS slew rate is a critical factor in optimizing radiated emissions, energy and duration of diode recovery spikes and switching voltage transients related to parasitics. This slew rate is predominantly determined by the rate of gate charge to the MOSFETs as shown in 图 8-9.

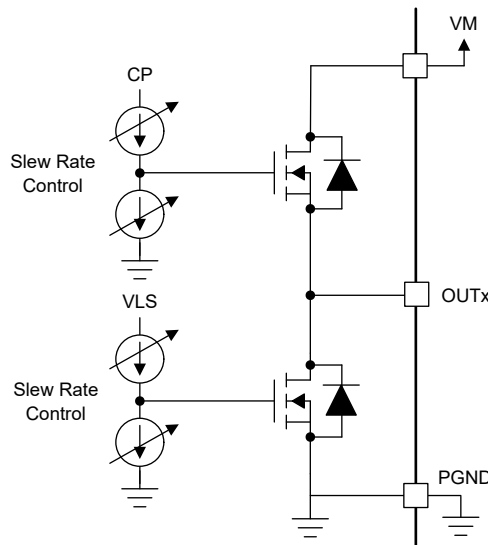


图 8-9. Slew Rate Control

The slew rate of each half-bridge can be adjusted by SLEW pin in hardware variant or by SLEW_RATE register in SPI variant. The slew rate is calculated by the rise-time and fall-time of the voltage on OUTx pin as shown in 图 8-10.

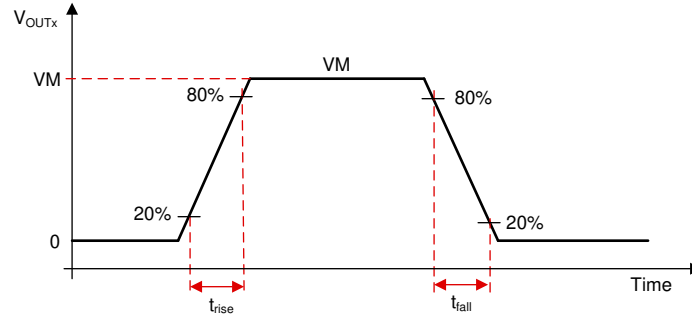


图 8-10. Slew Rate Measurement

8.3.7 Cross Conduction (Dead Time)

The device is fully protected against any cross conduction of MOSFETs - during the switching of high-side and low-side MOSFETs, DRV8317 avoids shoot-through events by inserting a dead time (t_{dead}). This is implemented by sensing the gate-source voltage (V_{GS}) of the high-side and low-side MOSFETs and ensuring that V_{GS} of high-side MOSFET has dropped below turn-off level before switching on the low-side MOSFET of same half-bridge (or vice-versa) as shown in 图 8-11 and 图 8-12. The V_{GS} of the high-side and low-side MOSFETs (V_{GS_HS} and V_{GS_LS}) shown in 图 8-12 are DRV8317 internal signals.

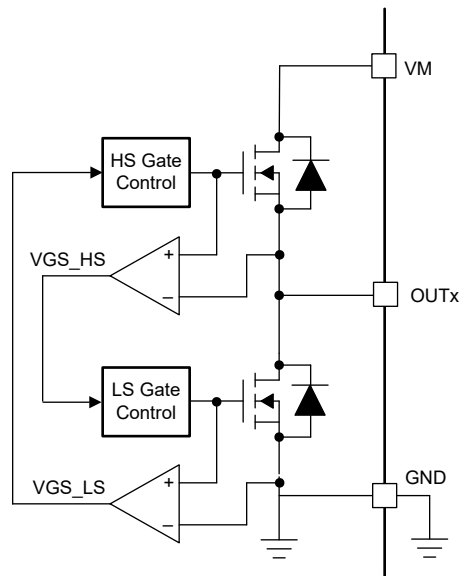


图 8-11. Cross Conduction Protection

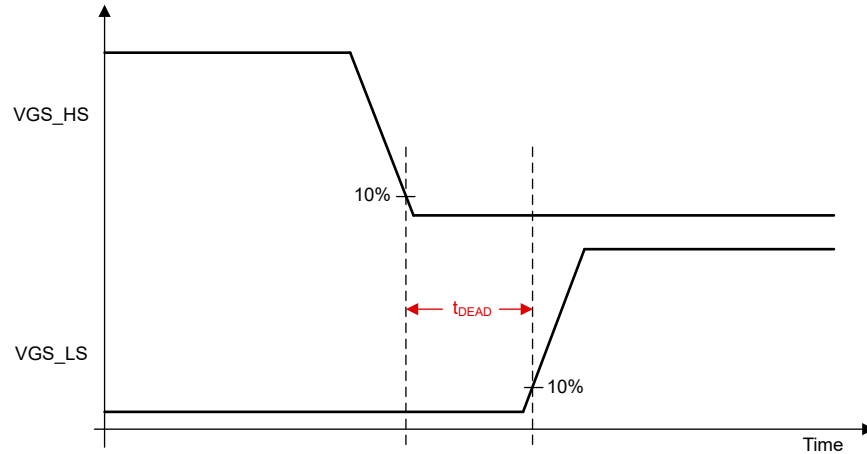


图 8-12. Dead Time

8.3.8 Propagation Delay

The propagation delay time (t_{pd}) is measured as the time between an input logic edge to change in OUTx voltage. The propagation delay time includes the input deglitch delay, analog driver delay, and depends on the slew rate setting. The input deglitcher prevents high-frequency noise on the input pins from affecting the output state of the gate drivers. To support multiple control modes, a small digital delay is added as the input command propagates through the device.

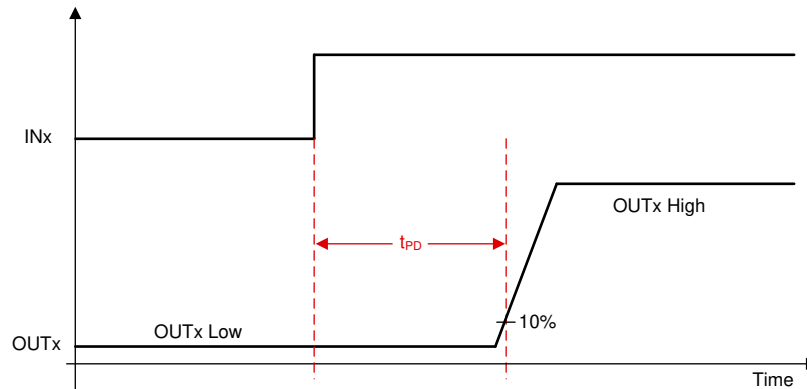


图 8-13. Propagation Delay

8.3.9 Pin Diagrams

This section presents the I/O structure of all digital input and output pins.

8.3.9.1 Logic Level Input Pin (Internal Pulldown)

图 8-14 shows the input structure for the logic levels pins INHx, INLx, nSLEEP, SCLK and SDI. The input can be driven with an external resistor to GND or an external logic voltage supply. It is recommended to pull these pins low in device sleep mode to reduce leakage current through the internal pull-down resistors.

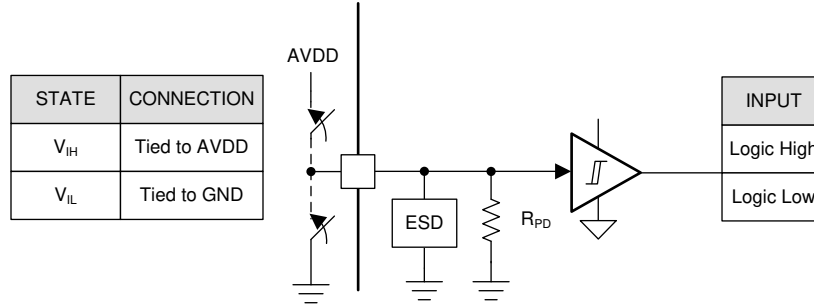


图 8-14. Logic-Level Input Pin Structure

8.3.9.2 Logic Level Input Pin (Internal Pullup)

图 8-15 显示了逻辑电平引脚 nSCS 的输入结构。该输入可以由外部电阻器连接到 GND 或外部逻辑电压供应驱动。

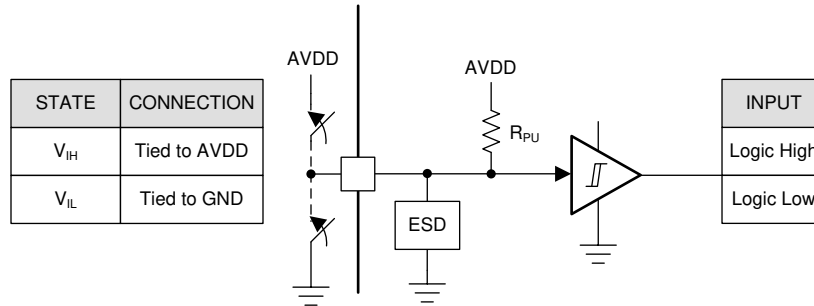


图 8-15. nSCS Input Pin Structure

8.3.9.3 Open Drain Pin

图 8-16 显示了开漏输出引脚 nFAULT 的结构。开漏输出需要外部上拉电阻器连接到逻辑电压供应才能正常工作。

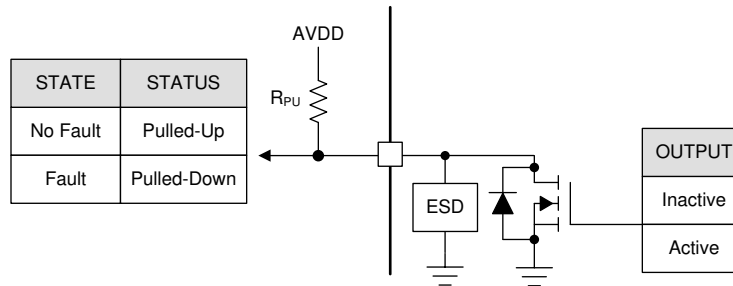


图 8-16. Open Drain Output Pin Structure

8.3.9.4 Push Pull Pin

图 8-17 显示了推挽引脚 SDO 的结构。

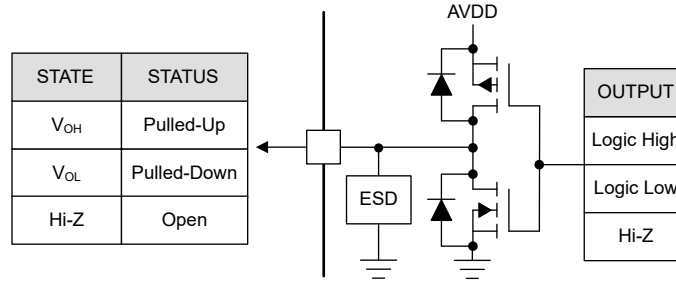


图 8-17. Push-Pull Output Pin Structure

8.3.9.5 Four Level Input Pin

图 8-18 shows the structure of the four level input pins GAIN, MODE and SLEW on hardware interface devices. The input can be set by tying the pin to AGND or AVDD, leaving the pin unconnected, or connecting an external resistor from the pin to ground.

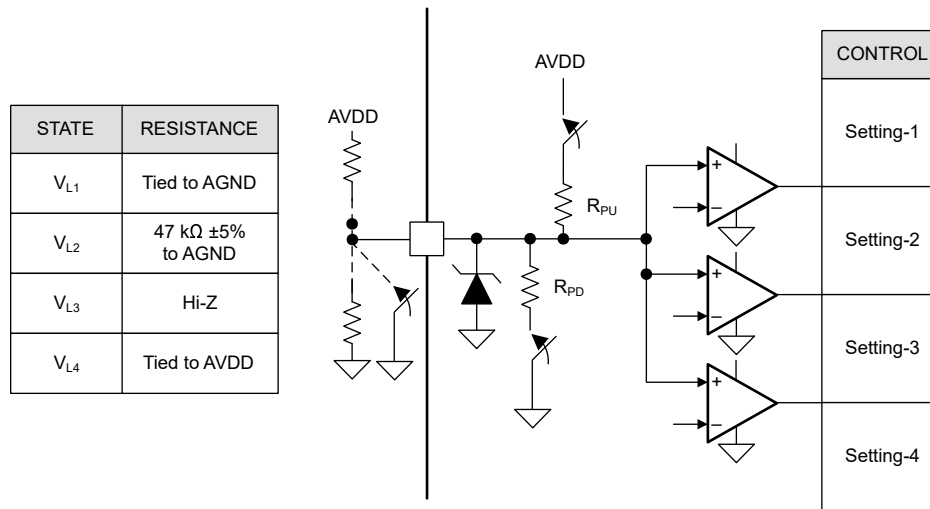


图 8-18. Four Level Input Pin Structure

8.3.10 Current Sense Amplifiers

The DRV8317 integrates three high-performance low-side current sense amplifiers for current measurements using built-in current sense. Low-side current measurements are commonly used to implement overcurrent protection, external torque control, or brushless DC commutation with the external controller. Each amplifier senses the current in the corresponding half-bridge when the low-side MOSFET is conducting. The current sense amplifiers include features such as configurable gain (through CSA_GAIN register or GAIN pin) and an external voltage reference (VREF) provided through CSAREF pin.

8.3.10.1 Current Sense Amplifier Operation

The SOx pin on the DRV8317 provides an analog voltage proportional to the current flowing in the low side MOSFETs (I_{OUTx}) multiplied by the gain setting (G_{CSA}) of the current sense amplifier. The gain setting is adjustable between four different levels which can be set by the GAIN pin (hardware variant) or the CSA_GAIN register (SPI variant).

图 8-19 shows the internal architecture of the current sense amplifiers. The current sense is implemented with a sense FET on each low-side FET of the DRV8317 device. This current information is converted in to a voltage based on the CSAREF pin (VREF) input and the CSA gain setting; this voltage is available on the SOx pin. The CSA output voltage can be calculated using [方程式 2](#)

$$SOx = V_{REF}/2 + (G_{CSA} * I_{OUTx}), \text{ wherein } I_{OUTx} \text{ is considered positive in the direction shown in 图 8-19.} \quad (2)$$

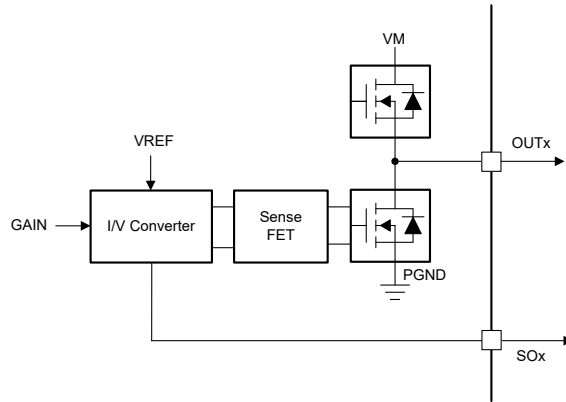


图 8-19. Integrated Current Sense Amplifier

图 8-20 shows the I_{OUTx} to CSA output transfer function. In bi-directional operation, the amplifier output for 0-A input is set at $V_{REF}/2$. Any change in the output phase current results in a corresponding change in the amplifier output as given in 方程式 2.

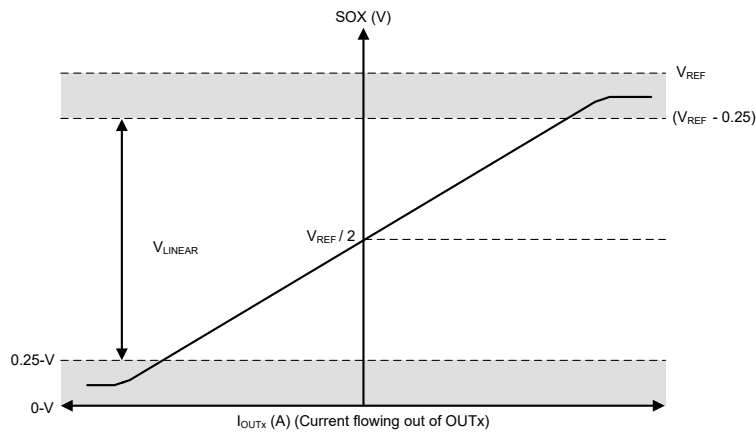


图 8-20. IOUTx to CSA Transfer Function

The amplifier has a defined linear region as shown in 图 8-21.

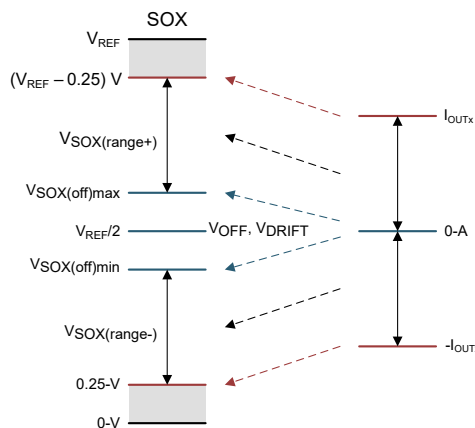


图 8-21. Bi-directional Current Sense Linear Region

备注

The current sense amplifiers use the external voltage reference (VREF) provided at the CSAREF pin.

8.3.11 Protections

The DRV8317 is protected against VM, VIN_AVDD, AVDD, CP under voltage, VM over voltage, SPI fault, OTP read fault, FET over current and FET, LDO over temperature events. 表 8-6 summarizes various fault details.

表 8-6. Fault Action and Response

FAULT	CONDITION	CONFIGURATION	REPORT	PRE-DRIVER	FAULT STATUS BITS	DIGITAL	RECOVERY
VM under voltage lockout (VM_UV)	$V_{VM} < V_{UVLO}$ (falling)	UVP_MODE = 00b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY and $V_{VM} > V_{UVLO}$ (rising)
		UVP_MODE = 01b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY and $V_{VM} > V_{UVLO}$ (rising)
VM under voltage warning (VMUV_WARN)	$V_{VM} < V_{VMUV_WARN_FALL}$	VMUV_WARN_MODE = 00b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY and $V_{VM} > V_{VMUV_WARN_RISE}$
		VMUV_WARN_MODE = 01b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY and $V_{VM} > V_{VMUV_WARN_RISE}$
		VMUV_WARN_MODE = 10b	nFAULT	Active	Latched	Active	No action; report only mode
		VMUV_WARN_MODE = 11b	—	Active	—	Active	—
VIN_AVDD under voltage (VIN_AVDD_UV)	$V_{VIN_AVDD} < V_{VIN_AVDD_UV}$ (falling)	—	—	Hi-Z	—	Reset	Automatic: $V_{VIN_AVDD} > V_{VIN_AVDD_UV}$ (rising)
AVDD under voltage (AVDD_UV)	$V_{AVDD} < V_{AVDD_UV}$ (falling)	—	—	Hi-Z	—	Reset	Automatic: $V_{AVDD} > V_{AVDD_UV}$ (rising)
Charge pump under voltage (CP_UV)	$V_{CP} < V_{CPIV}$ (falling)	UVP_MODE = 00b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY and $V_{CP} > V_{CPIV}$ (rising)
		UVP_MODE = 01b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY and $V_{CP} > V_{CPIV}$ (rising)
Over current protection (OCP)	$I_{PHASE} > I_{OCP}$	OCP_MODE = 000b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY
		OCP_MODE = 001b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY
		OCP_MODE = 010b	nFAULT	Hi-Z	Latched	Active	Latched: Cleared by FLT_CLR bit or nSLEEP reset pulse
		OCP_MODE = 011b	nFAULT	Active	Latched	Active	No action; report only mode
VM over voltage protection (VM_OV)	$V_{VM} > V_{OVP}$ (rising)	OVP_MODE = 00b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY and $V_{VM} < V_{OVP}$ (falling)
		OVP_MODE = 01b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY and $V_{VM} < V_{OVP}$ (falling)
SPI fault (SPIFLT)	SCLK fault and ADDR fault	SPIFLT_MODE = 0b	nFAULT	Active	Latched	Active	No action; report only mode
		SPIFLT_MODE = 1b	—	Active	—	Active	—
System (OTP read) (SYSFLT)	OTP read parity fault	—	nFAULT	Disabled	Latched	Active	Latched: Cleared by FLT_CLR bit or nSLEEP reset pulse
FET over temperature warning (OTW_FET)	$T_J > T_{OTW_FET}$	OTF_MODE = 00b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY and $T_J < T_{OTW_FET} - T_{OTW_FET_HYS}$
		OTF_MODE = 01b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY and $T_J < T_{OTW_FET} - T_{OTW_FET_HYS}$
FET over temperature shutdown (OTS_FET)	$T_J > T_{OTS_FET}$	OTF_MODE = 00b	nFAULT	Hi-Z	Latched	Active	Automatic: SLOW_TRETRY and $T_J < T_{OTS_FET} - T_{OTS_FET_HYS}$
		OTF_MODE = 01b	nFAULT	Hi-Z	Latched	Active	Automatic: FAST_TRETRY and $T_J < T_{OTS_FET} - T_{OTS_FET_HYS}$

表 8-6. Fault Action and Response (续)

FAULT	CONDITION	CONFIGURATION	REPORT	PRE-DRIVER	FAULT STATUS BITS	DIGITAL	RECOVERY
AVDD LDO over temperature shutdown (OTS_LDO)	$T_J > T_{OTS_LDO}$	—	—	Hi-Z	—	Reset	Automatic: $T_J < T_{OTS_LDO} - T_{OTS_LDO_HYS}$

8.3.11.1 Under Voltage Protection (UVP)

DRV8317 has under voltage protection enabled for VM, VIN_AVDD, AVDD and CP voltage rails - these fault protections cannot be disabled. VM, VIN_AVDD and AVDD under voltage faults result in device reset; CP under voltage fault response is user configurable through UVP mode.

VM, VIN_AVDD, AVDD Under Voltage Protection (VIN_AVDD_UV, AVDD_UV)

If at any time, the voltage on VIN_AVDD or AVDD pin falls below the corresponding under voltage falling threshold ($V_{VINAVDD_UV}$ or V_{AVDD_UV}), DRV8317 enters reset - in reset, FETs are in Hi-Z, pre-driver, charge pump, current sense amplifier and digital logic are disabled. Normal device operation resumes automatically after the respective rail voltage rises above the corresponding under voltage rising threshold ($V_{VINAVDD_UV}$ or V_{AVDD_UV}) as shown in 图 8-22.

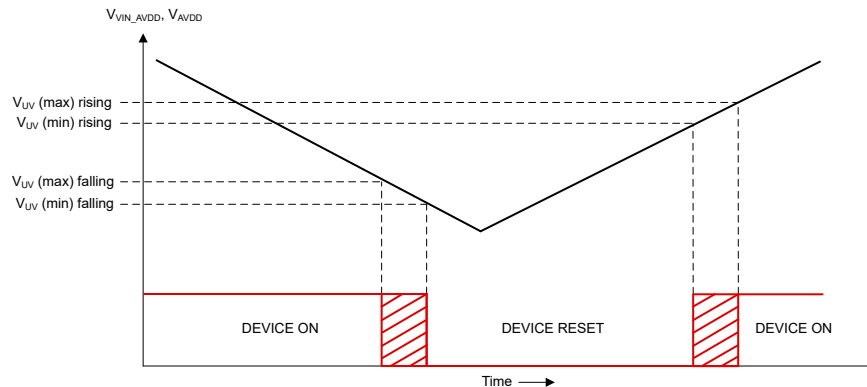


图 8-22. VIN_AVDD, AVDD Under Voltage Protection

VM, CP Under Voltage Protection (VM_UV, CP_UV)

If at any time the voltage on VM or CP pin falls below the corresponding under voltage falling threshold (V_{VM_UV} or V_{CP_UV}), FETs are in Hi-Z, charge pump is disabled, nFAULT pin is driven low, FAULT and UVP in DEV_STS and VM_UV or CP_UV in SUP_STS are set to 1b. Normal operation resumes automatically (pre-driver, charge pump operation and the nFAULT pin is released) once the retry time (t_{RETRY}) lapses after VM or CP voltage is above the corresponding under voltage rising threshold (V_{VM_UV} or V_{CP_UV}) as shown in 图 8-23. The FAULT, UVP and UV_UV or CP_UV bits stay set to 1b until a clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

Retry time (t_{RETRY}) is set by,

- Slow retry time (SLOW_TRETRY) by configuring UVP_MODE to 00b
- Fast retry time (FAST_TRETRY) by configuring UVP_MODE to 01b

IN DRV8317H, UVP_MODE is set to 01b and FAST_TRETRY is fixed at 5-ms.

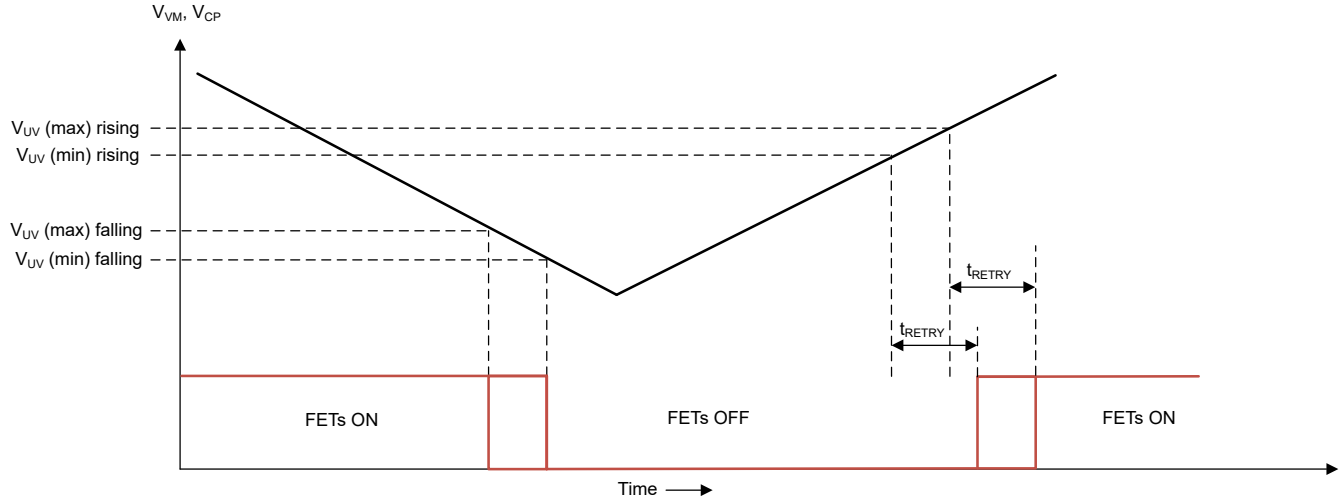


图 8-23. VM, CP Under Voltage Protection

8.3.11.2 VM Under Voltage Warn (VMUV_WARN) Protection

DRV8317 provides user configurable thresholds ($V_{VMUV_WARN_FALL}$, $V_{VMUV_WARN_RISE}$) for VM under voltage warn protection. If at any time, voltage on VM pin falls below the $V_{VMUV_WARN_FALL}$ threshold, action is taken as per VMUV_WARN_MODE configuration. There are four settings for VMUV_WARN_MODE: automatic retry with slow and fast retry time, report only and disabled. The threshold for the VM under voltage warn fault condition to be removed is set by $V_{VMUV_WARN_RISE}$. This fault can be enabled/ disabled using VMUV_WARN_EN. In DRV8317H, this fault is enabled by default and set to report only mode (VMUV_WARN_MODE set to 10b).

8.3.11.2.1 VM Under Voltage Warn Automatic Retry (VMUV_WARN_MODE = 00b or 01b)

After a VM under voltage warn event in this mode, all the FETs are in Hi-Z and the nFAULT pin is driven low. The FAULT, UVW bits (in DEV_STS register) and VMUV_WARN bit (in SUP_STS register) are set to 1b. Normal operation resumes automatically (pre-driver operation and the nFAULT pin is released) once the retry time (t_{RETRY}) time lapses after the VM pin voltage rises above the $V_{VMUV_WARN_RISE}$ threshold as shown in 图 8-24. The FAULT, UVW and VMUV_WARN bits stay set to 1b until clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

Retry time (t_{RETRY}) is set by,

- Slow retry time (SLOW_TRETRY) by configuring VPWR_MODE to 00b
- Fast retry time (FAST_TRETRY) by configuring VPWR_MODE to 01b

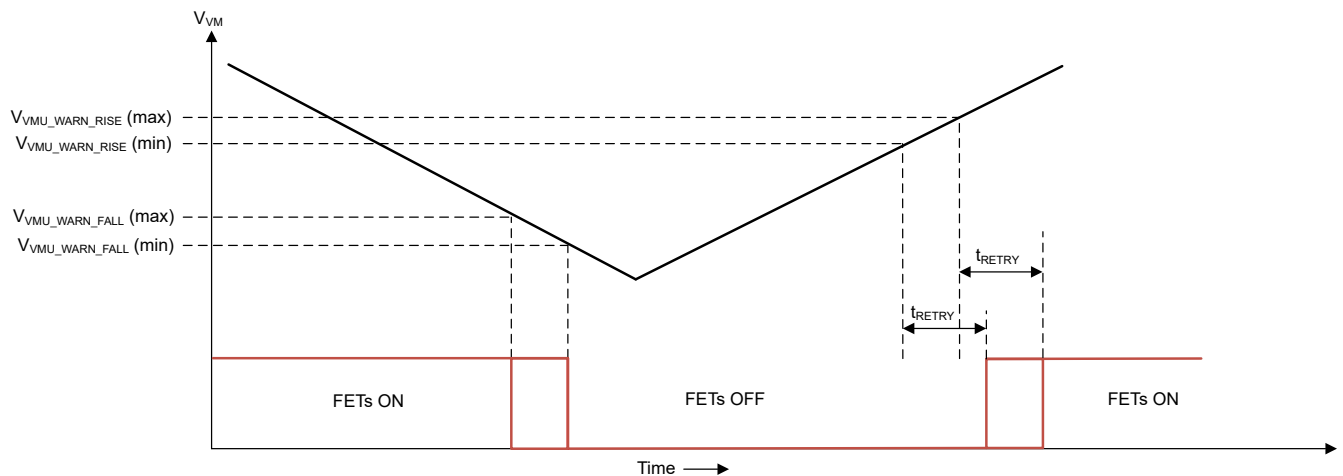


图 8-24. VM Under Voltage Warning

8.3.11.2.2 VM Under Voltage Warn Report Only (VMUV_WARN_MODE = 10b)

No protective action occurs after a VM under voltage warn event in this mode. The VM under voltage warn event is reported by driving the nFAULT pin low and setting the FAULT, UVW bits (in DEV_STS register) and VMUV_WARN bit (in SUP_STS register) to 1b. DRV8317 continues to operate as usual. The external controller manages the VM under voltage warn condition by acting appropriately. The reporting clears (nFAULT pin is released, FAULT, UVW and VMUV_WARN bits are set to 0b) when a clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

8.3.11.2.3 VM Under Voltage Warn Disabled (VMUV_WARN_MODE = 11b)

No action is taken and no reporting (nFAULT pin, status register bits) is done after a VM under voltage warn event in this mode.

8.3.11.3 Over Current Protection (OCP)

A MOSFET over current event is sensed by monitoring the current flowing through each of the FETs. If the current through a FET exceeds the OCP threshold (I_{OCP}) for longer than the OCP deglitch time (t_{OCP}), an OCP event is recognized and action is taken according to OCP_MODE. In order to avoid false trigger of OCP at PWM transitions, due to ringing in the phase voltage, there is a blanking time (t_{BLANK}) applied after each PWM edge. During blanking time, OCP events are ignored.

In DRV8317H, the t_{OCP} is fixed at 0.6- μ s (typical), t_{BLANK} is fixed at 0.7- μ s (typical) and the OCP_MODE is set to 001b with retry time of 5-ms. In DRV8317S, the t_{OCP} is configured by OCP_DEG, the t_{BLANK} is configured by OCP_TBLANK and the OCP_MODE can be configured in four different modes: OCP latched shutdown, OCP automatic retry with fast and slow retry times and OCP report only.

备注

($t_{OCP} + t_{BLANK}$) should not exceed 2- μ s

8.3.11.3.1 OCP Latched Fault (OCP_MODE = 010b)

After an OCP event in this mode, all MOSFETs are in Hi-Z and the nFAULT pin is driven low. The FAULT, OCP bits (in DEV_STS register) and corresponding FETs' OCP bits (in DRV_STS register) are set to 1b. Normal operation resumes (pre-driver operation, FAULT, OCP, corresponding FETs' OCP bits set to 0b and the nFAULT pin is released) when a clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

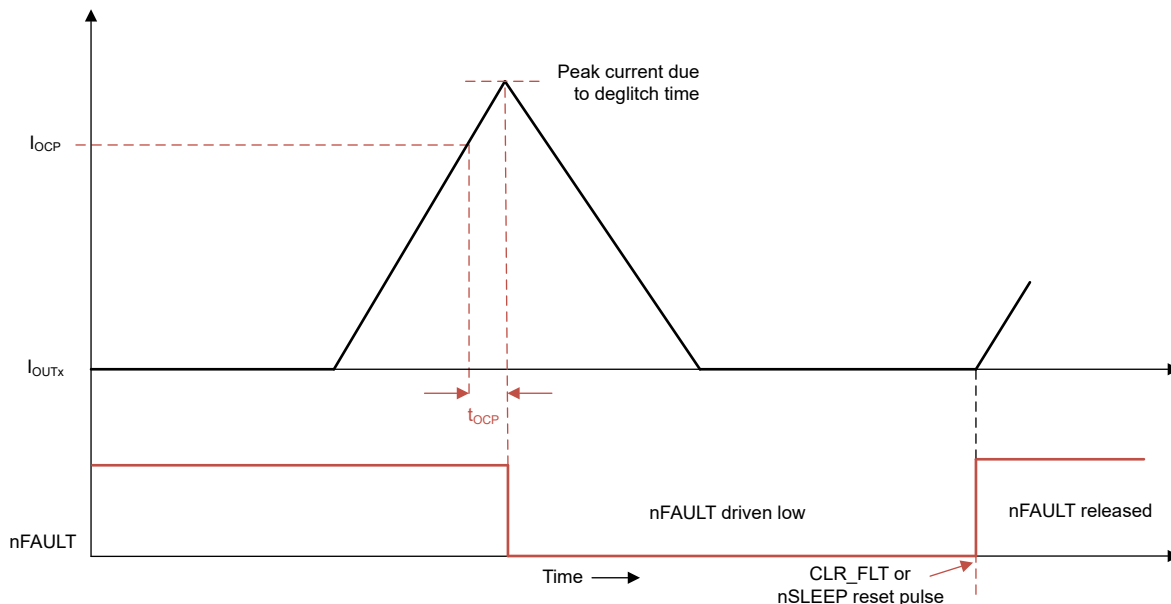


图 8-25. Over Current Protection - Latched Mode

8.3.11.3.2 OCP Automatic Retry (OCP_MODE = 000b or 001b)

After an OCP event in this mode, all the FETs are in Hi-Z and the nFAULT pin is driven low. The FAULT, OCP bits (in DEV_STS register) and corresponding FETs' OCP bits (in DRV_STS register) are set to 1b. Normal operation resumes automatically (pre-driver operation, the nFAULT pin is released and corresponding FETs' OCP bits are set to 0b) after the retry time (t_{RETRY}) time elapses. The FAULT and OCP bits stay set to 1b until clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

Retry time (t_{RETRY}) is set by,

- Slow retry time (SLOW_TRETRY) by configuring OCP_MODE to 000b
- Fast retry time (FAST_TRETRY) by configuring OCP_MODE to 001b

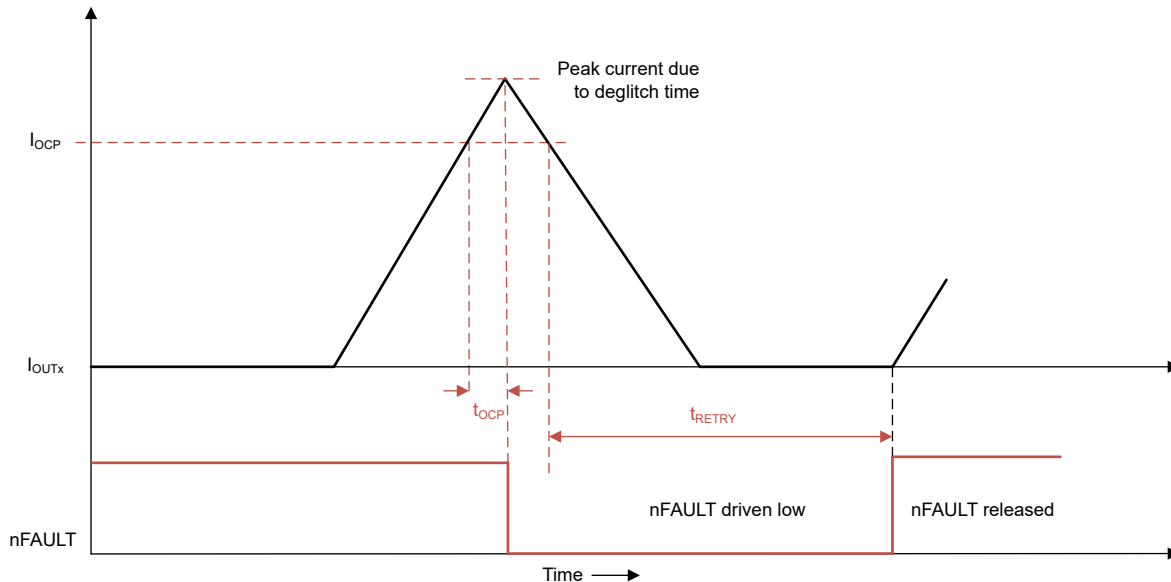


图 8-26. Over Current Protection - Automatic Retry Mode

8.3.11.3.3 OCP Report Only (OCP_MODE = 011b)

No protective action occurs after an OCP event in this mode. The over current event is reported by driving the nFAULT pin low and setting the FAULT, OCP bits (in DEV_STS register) and corresponding FETs' OCP bits (in DRV_STS register) to 1b. DRV8317 continues to operate as usual. The external controller manages the over current condition by acting appropriately. The reporting clears (nFAULT pin is released, FAULT, OCP, and corresponding FETs' OCP bits are set to 0b) when a clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

8.3.11.4 VM Over Voltage Protection (OVP)

If at any time, input supply voltage on the VM pin rises higher than the V_{OVP} rising threshold, all the integrated FETs are in Hi-Z, FAULT, OVP bits (in DEV_STS register) and VM_OV (in SUP_STS register) are set to 1b and the nFAULT pin is driven low. Normal operation resumes automatically (pre-driver operation and the nFAULT pin is released) once retry time (t_{RETRY}) lapses after VM pin voltage is below the V_{OVP} falling threshold as shown in 图 8-27. The FAULT, OVP and VM_OV bits stay set to 1b until clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

Retry time (t_{RETRY}) is set by,

- Slow retry time (SLOW_TRETRY) by configuring OVP_MODE to 00b
- Fast retry time (FAST_TRETRY) by configuring OVP_MODE to 01b

IN DRV8317H, OVP_MODE is set to 01b and FAST_TRETRY is fixed at 5-ms.

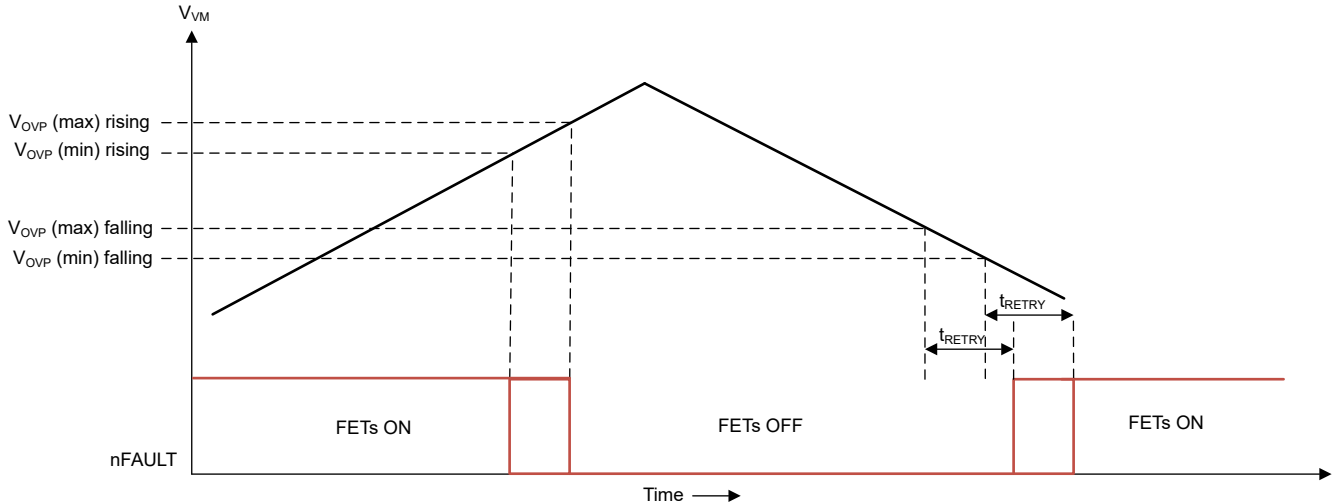


图 8-27. VM Over Voltage Protection

8.3.11.5 SPI Fault

In the event of a SPI transaction fault (parity, frame or bus contention error), if SPLIFLT_MODE is set to 0b, nFAULT is driven low, FAULT, SPIFLT bits (in DEV_STS register) and SPI_PARITY/ BUS_CNT/ FRM_ERR bits (in SYSIF_STS register) are set to 1b. DRV8317 continues to operate as usual. The external controller manages the SPI fault event by acting appropriately. The reporting clears (nFAULT pin is released, FAULT, SPIFLT, and SPI_PARITY/ BUS_CNT/ FRM_ERR bits are set to 0b) when a clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}).

If SPIFLT_MODE is set to 1b, SPI fault is disabled and reporting (nFAULT, status register bits) does not happen on a SPI fault event.

8.3.11.6 System (OTP Read) Fault

DRV8317 loads the configurable register settings from the OTP on every power-up cycle. If an OTP read fault is encountered while configuring the registers, pre-driver is disabled, FAULT, SYSFLT bits (in DEV_STS register) and OTPLD_ERR bit (in SYSIF_STS register) are set to 1b and nFAULT is driven low. Normal operation resumes (pre-driver, FAULT, SYSFLT, OTPLD_ERR bits set to 0b and nFAULT pin is released) when a clear fault command is issued either through the FLT_CLR bit or an nSLEEP reset pulse (t_{RST}). It is advisable not to operate DRV8317 by issuing a clear fault command in the event of a OTP read fault since the register settings may be in an unknown state and may lead to unexpected device operation.

8.3.11.7 Thermal Protection

DRV8317 has over temperature warning (OTW) and over temperature shutdown (OTS) features for protection against over temperature events. OTW is available for FET protection (OTW_FET) while OTS is available for FET (OTS_FET) and AVDD LDO (OTS_LDO) protection.

8.3.11.7.1 FET Over Temperature Warning (OTW_FET)

If the FET temperature exceeds the over temperature warning (T_{OTW_FET}) threshold, the FAULT, OTF bits (in DEV_STS register) and OTW_FET bit (in OT_STS register) are set to 1b and the nFAULT pin is driven low. The nFAULT pin is released and OTW_FET is set to 0b once retry time (t_{RETRY}) elapses after the FET temperature falls below the over temperature warning ($T_{OTW_FET} - T_{OTW_FET_HYS}$) threshold. The FAULT, OTF bits stay set to 1b until cleared through the CLR_FLT bit or an nSLEEP reset pulse (t_{RST}).

Retry time (t_{RETRY}) is set by,

- Slow retry time (SLOW_TRETRY) by configuring OTF_MODE to 00b
- Fast retry time (FAST_TRETRY) by configuring OTF_MODE to 01b

In DRV8317H, FET over temperature warning is disabled.

8.3.11.7.2 FET Over Temperature Shutdown (OTS_FET)

If the FET temperature exceeds the shutdown threshold (T_{OTS_FET}), all the integrated FETs are in Hi-Z, the FAULT, OTF bits (in DEV_STS register) and OTS_FET bit (in OT_STS register) are set to 1b and the nFAULT pin is driven low. Normal operation resumes automatically (pre-driver operation, nFAULT pin is released and OTS_FET is set to 0b) after retry time (t_{RETRY}) elapses, if FET temperature falls below the over temperature shutdown ($T_{OTS_FET} - T_{OTS_FET_HYS}$) threshold. The FAULT, OTF bits stay set to 1b until cleared through the CLR_FLT bit or an nSLEEP reset pulse (t_{RST}). This feature cannot be disabled.

Retry time (t_{RETRY}) is set by,

- Slow retry time (SLOW_TRETRY) by configuring OTF_MODE to 00b
- Fast retry time (FAST_TRETRY) by configuring OTF_MODE to 01b

IN DRV8317H, t_{RETRY} period is fixed at 5-ms.

8.3.11.7.3 LDO Over Temperature Shutdown

If AVDD LDO temperature exceeds the LDO over temperature shutdown (T_{OTS_LDO}) threshold, all the integrated FETs are in Hi-Z and device enters reset. Normal operation resumes automatically when AVDD LDO temperature falls below the over temperature shutdown threshold ($T_{OTS_LDO} - T_{OTS_LDO_HYS}$). This feature cannot be disabled.

8.4 Device Functional Modes

8.4.1 Functional Modes

8.4.1.1 Sleep Mode

The nSLEEP pin manages the state of DRV8317. When the nSLEEP pin is low, the device goes to a low-power sleep mode. In sleep mode MOSFETs, current sense amplifiers, charge pump, AVDD regulator and SPI bus are disabled. The t_{SLEEP} time must elapse after a falling edge on the nSLEEP pin before the device goes to sleep mode. The device comes out of sleep mode automatically if the nSLEEP pin is pulled high. The t_{WAKE} time must elapse before the device is ready for PWM inputs.

备注

During power up and power down of the device through the nSLEEP pin, the nFAULT pin is held low as the internal regulators are enabled or disabled. After the regulators have enabled or disabled, the nFAULT pin is automatically released. The duration that the nFAULT pin is low does not exceed the t_{SLEEP} or t_{WAKE} time.

8.4.1.2 Operating Mode

When the nSLEEP pin is high and the V_{VM} voltage is greater than the V_{UVLO} voltage, the device goes to operating mode. The t_{WAKE} time must elapse before the device is ready for inputs. In this mode the charge pump, AVDD regulator and SPI bus are active.

8.4.1.3 Fault Reset (FLT_CLR or nSLEEP Reset Pulse)

In the case of latched faults, DRV8317 turns off the MOSFETs (Hi-Z) and the motor coasts to a stop.

When the fault condition clears, the device can go to the operating state again by either setting the FLT_CLR bit to 1b in the SPI variant or by issuing a reset pulse on the nSLEEP pin in the hardware variant. The nSLEEP reset pulse (t_{RST}) consists of a high-to-low-to-high transition on the nSLEEP pin. The low period of the sequence should fall with the t_{RST} time window or else the device will start the complete shutdown sequence. The reset pulse has no effect on any of the regulators, device settings, or other functional blocks.

8.5 SPI Communication

8.5.1 Programming

8.5.1.1 SPI Format

SPI Format - with Parity

The SDI input data word is 24 bits long and consists of the following format:

- 1 read or write bit, W (bit B23)
- 6 address bits, A (bits B22 through B17)
- Parity bit, P (bit B16)
- 15 data bits with 1 parity bit, D (bits B15 through B0)

The SDO output data word is 24 bits long. The most significant bits are status bits and the least significant 16 bits are the data content of the register being accessed.

表 8-7. SDI Input Data Word Format for SPI

R/W	ADDRESS						PAR ITY	PAR ITY	DATA															
B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0	
W0	A5	A4	A3	A2	A1	A0	P	P	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	

表 8-8. SDO Output Data Word Format

STATUS								DATA															
B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0
S7	S6	S5	S4	S3	S2	S1	S0	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

The details of the bits used in SPI frame format are detailed below.

Read/Write Bit (R/W): R/W (W0) bit set to 0b indicates a SPI write transaction. For a SPI read operation, R/W bit needs to be set to 1b.

Address Bits (A): A SPI secondary device takes a 6-bit register address.

Parity Bit (P): Both header and data fields of a SPI input data frame include a parity bit for single bit error detection - in 表 8-7, B16 is parity bit for the header field, while B15 is the parity bit for the data field. The parity scheme used is even parity - the number of ones in a block of 16-bits (including the parity bit) is even. Data will be written to the internal registers only if the parity check is successful. Parity checks can be enabled or disabled by configuring the SPI_PEN bit of SYS_CTRL register. Parity checks are disabled by default.

备注

Though parity checks are disabled by default, TI recommends enabling parity checks to safeguard against single-bit errors.

Error Handling

Parity Error: Upon detecting a parity error, the secondary device responds in the following ways. Parity error gets latched and reported on nFAULT. The error status is available for read on SPI_PARITY field of SYS_STS register. A parity error in the header will not prevent the secondary device from responding with data. The SDO will be driven by the secondary device being addressed. Updates to write address pointer and the device registers will be ignored when parity error is detected. In a sequential write, upon detection of parity error any subsequent register writes will be ignored.

Frame Error: Any incomplete SPI Frame will be reported as Frame error. Frame errors will be latched in FRM_ERR field of SYSIF_STS register and indicated on nFAULT.

SPI Read/Write Sequence

SPI Read Sequence: The SPI read transaction comprises of an 8-bit header (R/W - 1 bit, Address - 6 bits, and parity -1 bit) followed by 16-bit dummy data words. Upon receiving the first byte of header, the secondary device responds with an 8-bit device status information. The read address pointer gets updated immediately after receiving the address field of the header. The read address from the header acts as the starting address for the register reads. The read address pointer gets incremented automatically upon completion of a 16-bit transfer. The length of data transfer is not restricted by the secondary device. The secondary device responds with data as long as the primary device transmits dummy words. If parity error check is enabled, the MSB of read data will be replaced with computed parity bit

SPI Write Sequence: SPI write transaction comprises of an 8-bit header followed by 16-bit data words to be written into the register bank. Similar to a read transaction, the addressed secondary device responds with an 8-bit device status information upon receiving the first byte of header. Once the header bytes are received, the write address pointer gets updated. The write address from the header acts as the starting address for sequential register writes. The read address pointer will retain the address of the register being read in the previous SPI transaction. The length of data transfer is not restricted by the secondary device. Both read and write address pointers will be incremented automatically upon completion of a 16-bit transfer. While receiving data from the primary device, the SDO will be driven with the register data addressed by read address pointer.

8.6 DRV8317 Registers

表 8-9 lists the memory-mapped registers for the DRV8317 registers. All register offset addresses not listed in 表 8-9 should be considered as reserved locations and the register contents should not be modified.

表 8-9. DRV8317 Registers

Offset	Acronym	Register Name	Section
0h	DEV_STS	Device Status Register	DEV_STS Register (Offset = 0h) [Reset = 0280h]
2h	DEV_RSTS	Device Raw Status Register	DEV_RSTS Register (Offset = 2h) [Reset = 0000h]
4h	OT_STS	Over Temperature Status Register	OT_STS Register (Offset = 4h) [Reset = 0000h]
5h	SUP_STS	Supply Status Register	SUP_STS Register (Offset = 5h) [Reset = 0000h]
6h	DRV_STS	Driver Status Register	DRV_STS Register (Offset = 6h) [Reset = 0000h]
7h	SYSIF_STS	System Interface Status Register	SYSIF_STS Register (Offset = 7h) [Reset = 0000h]
10h	FLT_MODE	Fault Mode Register	FLT_MODE Register (Offset = 10h) [Reset = 0015h]
12h	SYSF_CTRL	System Fault Control Register	SYSF_CTRL Register (Offset = 12h) [Reset = 0553h]
13h	DRVF_TCTRL	Driver Fault Control Register	DRVF_TCTRL Register (Offset = 13h) [Reset = 0155h]
16h	FLT_TCTRL	Fault Timing Control Register	FLT_TCTRL Register (Offset = 16h) [Reset = 0003h]
17h	FLT_CLR	Fault Clear Register	FLT_CLR Register (Offset = 17h) [Reset = 0000h]
18h	VMUV_WARN_THR	VM Under Voltage Warn Threshold Register	VMUV_WARN_THR Register (Offset = 18h) [Reset = 0000h]
20h	PWM_CTRL	PWM Control Register	PWM_CTRL Register (Offset = 20h) [Reset = 0000h]
22h	DRV_CTRL	Predriver control Register	DRV_CTRL Register (Offset = 22h) [Reset = 0003h]
23h	CSA_CTRL	CSA Control Register	CSA_CTRL Register (Offset = 23h) [Reset = 0008h]
3Fh	SYS_CTRL	System Control Register	SYS_CTRL Register (Offset = 3Fh) [Reset = 5008h]

Complex bit access types are encoded to fit into small table cells. 表 8-10 shows the codes that are used for access types in this section.

表 8-10. DRV8317 Access Type Codes

Access Type	Code	Description
Read Type		
R	R	Read
R-0	R-0	Read Returns 0s
Write Type		
W	W	Write
Reset or Default Value		
-n		Value after reset or the default value

8.6.1 DEV_STS Register (Offset = 0h) [Reset = 0280h]

DEV_STS is shown in [图 8-28](#) and described in [表 8-11](#).

Return to the [Summary Table](#).

图 8-28. DEV_STS Register

15	14	13	12	11	10	9	8
PARITY	RESERVED					DNRDY_STS	SYSFLT
R-0h	R-0-0h					R-0-1h	R-0h
7	6	5	4	3	2	1	0
RESET	SPIFLT	OCP	UVW	OVP	UVP	OTF	FAULT
R-1h	R-0h	R-0h	R-0h	R-0h	R-0h	R-0h	R-0h

表 8-11. DEV_STS Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-10	RESERVED	R-0	0h	Reserved
9	DNRDY_STS	R-0	1h	Device not ready status 0h = Device is ready to spin motor 1h = Device is not ready
8	SYSFLT	R	0h	OTP read fault occurred. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No OTP read fault is detected 1h = OTP read fault detected
7	RESET	R	1h	Device power on status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = Cleared by writing 1b to FLT_CLR bit after power-up 1h = Device has undergone power on reset
6	SPIFLT	R	0h	SPI fault status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No SPI fault is detected 1h = SPI fault is detected
5	OCP	R	0h	Driver over current Status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No over current condition is detected 1h = Over current condition is detected
4	UVW	R	0h	VM under voltage warning fault status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No VM under voltage warn condition is detected 1h = VM under voltage warn condition is detected
3	OVP	R	0h	Over voltage status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No over voltage condition is detected 1h = Over voltage condition is detected
2	UVP	R	0h	Supply under voltage status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No under voltage condition is detected on VM or CP 1h = Under voltage condition is detected on VM or CP
1	OTF	R	0h	Over temperature fault status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No over temperature warning / shutdown is detected 1h = Over temperature warning / shutdown is detected
0	FAULT	R	0h	Device fault status. Status remains latched until cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No fault condition is detected 1h = Fault condition is detected

8.6.2 DEV_RSTS Register (Offset = 2h) [Reset = 0000h]

DEV_RSTS is shown in 图 8-29 and described in 表 8-12.

Return to the [Summary Table](#).

图 8-29. DEV_RSTS Register

15	14	13	12	11	10	9	8
RESERVED						DNRDY_RSTS	SYSF_RSTS
R-0-0h						R-0h	R-0h
7	6	5	4	3	2	1	0
RESERVED	SPIF_RSTS	OCP_RSTS	VMUV_WRSTS	OVP_RSTS	UVP_RSTS	OTF_RSTS	RESERVED
R-0-0h	R-0h	R-0h	R-0-0h	R-0-0h	R-0h	R-0h	R-0-0h

表 8-12. DEV_RSTS Register Field Descriptions

Bit	Field	Type	Reset	Description
15-10	RESERVED	R-0	0h	Reserved
9	DNRDY_RSTS	R	0h	Device not ready indicator 0h = Device not ready to drive PWMs 1h = Device ready to drive PWMs
8	SYSF_RSTS	R	0h	OTP parity error during load, raw status. Cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No parity error during OTP load 1h = Parity error occurred during OTP load
7	RESERVED	R-0	0h	Reserved
6	SPIF_RSTS	R	0h	SPI fault raw status. Cleared by write to FLT_CLR or reset pulse on nSLEEP 0h = No SPI fault is detected 1h = SPI fault is detected
5	OCP_RSTS	R	0h	Driver OCP raw status. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current condition is detected 1h = Over current condition is detected
4	VMUV_WRSTS	R-0	0h	VM under voltage warning fault raw status. Auto cleared if retry is enabled in VMUV_WARN_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No VM under voltage warn condition is detected (VM > VMUV_WARN_RISE threshold) 1h = VM under voltage warn condition is detected (VM < VMUV_WARN_FALL threshold)
3	OVP_RSTS	R-0	0h	Over voltage protection fault raw status. Auto cleared if retry is enabled in OVP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over voltage condition on VM is detected 1h = VM over voltage condition is detected
2	UVP_RSTS	R	0h	Under voltage protection fault raw status. Auto cleared if retry is enabled in UVP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No under voltage condition is detected on VM or CP 1h = Under voltage condition is detected on VM or CP
1	OTF_RSTS	R	0h	Over temperature fault raw status. Auto cleared if retry is enabled in OTF_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over temperature warning/shutdown is detected 1h = Over temperature warning/shutdown is detected
0	RESERVED	R-0	0h	Reserved

8.6.3 OT_STS Register (Offset = 4h) [Reset = 0000h]

OT_STS is shown in [图 8-30](#) and described in [表 8-13](#).

Return to the [Summary Table](#).

图 8-30. OT_STS Register

15	14	13	12	11	10	9	8
PARITY		RESERVED					
R-0h		R-0-0h					
7	6	5	4	3	2	1	0
RESERVED					RESERVED	OTW_FET	OTS_FET
R-0-0h					R-0h	R-0h	R-0h

表 8-13. OT_STS Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-3	RESERVED	R-0	0h	Reserved
2	RESERVED	R	0h	Reserved
1	OTW_FET	R	0h	FET over temperature warning fault status. Auto cleared if retry is enabled in OTF_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No FET over temperature warning is detected 1h = FET over temperature warning is detected
0	OTS_FET	R	0h	FET over temperature shutdown fault status. Auto cleared if retry is enabled in OTF_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No FET over temperature shutdown is detected 1h = FET over temperature shutdown is detected

8.6.4 SUP_STS Register (Offset = 5h) [Reset = 0000h]

SUP_STS is shown in [图 8-31](#) and described in [表 8-14](#).

Return to the [Summary Table](#).

图 8-31. SUP_STS Register

15	14	13	12	11	10	9	8
PARITY	RESERVED						
R-0h	R-0-0h						
7	6	5	4	3	2	1	0
VMUV_WARN	VM_OV	RESERVED	CP_UV	RESERVED	RESERVED	VM_UV	RESERVED
R-0-0h	R-0-0h	R-0-0h	R-0h	R-0-0h	R-0h	R-0-0h	R-0h

表 8-14. SUP_STS Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-8	RESERVED	R-0	0h	Reserved
7	VMUV_WARN	R-0	0h	VM under voltage warning fault status. This bit is not auto cleared even when retry is enabled in VMUV_WARN_MODE. Can be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No VM under voltage warning is detected 1h = VM under voltage warning is detected
6	VM_OV	R-0	0h	VM over voltage fault status. This bit is not auto cleared even when retry is enabled in OVP_MODE. Can be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No VM over voltage is detected 1h = VM over voltage is detected
5	RESERVED	R-0	0h	Reserved
4	CP_UV	R	0h	Charge pump under voltage fault status. This bit is not auto cleared even when retry is enabled in UVP_MODE. Can be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No charge pump under voltage is detected 1h = Charge pump under voltage is detected
3	RESERVED	R-0	0h	Reserved
2	RESERVED	R	0h	Reserved
1	VM_UV	R-0	0h	VM under voltage fault status. This bit is not auto cleared even when retry is enabled in UVP_MODE. Can be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No VM under voltage is detected 1h = VM under voltage is detected
0	RESERVED	R	0h	Reserved

8.6.5 DRV_STS Register (Offset = 6h) [Reset = 0000h]

DRV_STS is shown in [图 8-32](#) and described in [表 8-15](#).

Return to the [Summary Table](#).

图 8-32. DRV_STS Register

15	14	13	12	11	10	9	8
PARITY	RESERVED						
R-0h	R-0-0h						
7	6	5	4	3	2	1	0
RESERVED	OCPC_HS	OCPB_HS	OCA_HS	RESERVED	OCPC_LS	OCPB_LS	OCA_LS
R-0-0h	R-0h	R-0h	R-0h	R-0-0h	R-0h	R-0h	R-0h

表 8-15. DRV_STS Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-7	RESERVED	R-0	0h	Reserved
6	OCPC_HS	R	0h	Over current status on high-side MOSFET of OUTC. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current detected on high-side MOSFET of OUTC 1h = Over current detected on high-side MOSFET of OUTC
5	OCPB_HS	R	0h	Over current status on high-side MOSFET of OUTB. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current detected on high-side MOSFET of OUTB 1h = Over current detected on high-side MOSFET of OUTB
4	OCPA_HS	R	0h	Over current status on high-side MOSFET of OUTA. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current detected on high-side MOSFET of OUTA 1h = Over current detected on high-side MOSFET of OUTA
3	RESERVED	R-0	0h	Reserved
2	OCPC_LS	R	0h	Over current status on low-side MOSFET of OUTC. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current detected on low-side MOSFET of OUTC 1h = Over current detected on low-side MOSFET of OUTC
1	OCPB_LS	R	0h	Over current status on low-side MOSFET of OUTB. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current detected on low-side MOSFET of OUTB 1h = Over current detected on low-side MOSFET of OUTB
0	OCPA_LS	R	0h	Over current status on low-side MOSFET of OUTA. Auto cleared if retry is enabled in OCP_MODE. Can also be cleared by write to FLT_CLR or reset pulse on nSLEEP. 0h = No over current detected on low-side MOSFET of OUTA 1h = Over current detected on low-side MOSFET of OUTA

8.6.6 SYSIF_STS Register (Offset = 7h) [Reset = 0000h]

SYSIF_STS is shown in 图 8-33 and described in 表 8-16.

Return to the [Summary Table](#).

图 8-33. SYSIF_STS Register

15	14	13	12	11	10	9	8
PARITY	RESERVED						
R-0h	R-0-0h						
7	6	5	4	3	2	1	0
RESERVED			OTPLD_ERR	RESERVED	SPI_PARITY	BUS_CNT	FRM_ERR
R-0-0h			R-0h	R-0-0h	R-0h	R-0h	R-0h

表 8-16. SYSIF_STS Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-5	RESERVED	R-0	0h	Reserved
4	OTPLD_ERR	R	0h	OTP parity error during load 0h = No OTP read error is detected 1h = OTP read error is detected
3	RESERVED	R-0	0h	Reserved
2	SPI_PARITY	R	0h	SPI parity error 0h = No SPI Parity Error is detected 1h = SPI Parity Error is detected
1	BUS_CNT	R	0h	SPI bus contention error 0h = No SPI Bus Contention Error is detected 1h = SPI Bus Contention Error is detected
0	FRM_ERR	R	0h	SPI frame error 0h = No SPI Frame Error is detected 1h = SPI Frame Error is detected

8.6.7 FLT_MODE Register (Offset = 10h) [Reset = 0015h]

FLT_MODE is shown in [图 8-34](#) and described in [表 8-17](#).

Return to the [Summary Table](#).

图 8-34. FLT_MODE Register

15	14	13	12	11	10	9	8
PARITY	RESERVED		VMUV_WARN_MODE		OVP_MODE		RESERVED
R/W-0h	R-0-0h		R/W-0h		R/W-0h		R/W-0h
7	6	5	4	3	2	1	0
SPIFLT_MODE	OCP_MODE			UVP_MODE		OTF_MODE	
R/W-0h	R/W-1h			R/W-1h		R/W-1h	

表 8-17. FLT_MODE Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-13	RESERVED	R-0	0h	Reserved
12-11	VMUV_WARN_MODE	R/W	0h	VM under voltage warning fault mode 0h = Report on nFAULT, latch into status register, pre-driver Hi-Z, auto recovery with slow retry time (in ms) 1h = Report on nFAULT, latch into status register, pre-driver Hi-Z, auto recovery with fast retry time (in ms) 2h = Report on nFAULT, latch into status register, no action on pre-driver 3h = Disabled
10-9	OVP_MODE	R/W	0h	Over voltage protection fault mode 0h = Report on nFAULT, latch into status register, pre-driver Hi-Z, auto recovery with slow retry time (in ms) 1h = Report on nFAULT, latch into status register, pre-driver Hi-Z, auto recovery with fast retry time (in ms) 2h = Reserved 3h = Reserved
8	RESERVED	R/W	0h	Reserved
7	SPIFLT_MODE	R/W	0h	SPI fault mode 0h = Report on nFAULT, latch into status register, no action on pre-driver 1h = Disabled
6-4	OCP_MODE	R/W	1h	Over current protection fault mode 0h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, auto recovery with slow retry time (in ms) 1h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, auto recovery with fast retry time (in ms) 2h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, no auto recovery, wait for CLR_FLT 3h = Report on nFAULT, Latch into status register, No action on pre-driver 4h = Reserved 5h = Reserved 6h = Reserved 7h = Reserved
3-2	UVP_MODE	R/W	1h	Under voltage protection fault mode 0h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, auto recovery with slow retry time (in ms) 1h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, auto recovery with fast retry time (in ms) 2h = Reserved 3h = Reserved

表 8-17. FLT_MODE Register Field Descriptions (续)

Bit	Field	Type	Reset	Description
1-0	OTF_MODE	R/W	1h	Over temperature fault mode 0h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, auto recover with Slow Retry time (in ms) 1h = Report on nFAULT, Latch into status register, pre-driver Hi-Z, auto recover with Fast Retry time (in ms) 2h = Reserved 3h = Reserved

8.6.8 SYSF_CTRL Register (Offset = 12h) [Reset = 0553h]

SYSF_CTRL is shown in [图 8-35](#) and described in [表 8-18](#).

Return to the [Summary Table](#).

图 8-35. SYSF_CTRL Register

15	14	13	12	11	10	9	8
PARITY	RESERVED				DNRDY_EN	OTW_FET_EN	RESERVED
R/W-0h	R-0-0h				R/W-1h	R/W-0h	R/W-1h
7	6	5	4	3	2	1	0
VMUV_WARN_EN	RESERVED	RESERVED	RESERVED	RESERVED		RESERVED	RESERVED
R/W-0h	R/W-1h	R-0-0h	R/W-1h	R-0-0h		R/W-1h	R/W-1h

表 8-18. SYSF_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-11	RESERVED	R-0	0h	Reserved
10	DNRDY_EN	R/W	1h	Device not ready fault enable 0h = Device not ready fault is disabled 1h = Device not ready fault is enabled
9	OTW_FET_EN	R/W	0h	FET over temperature warning fault enable 0h = FET over temperature warning is disabled 1h = FET over temperature warning is enabled
8	RESERVED	R/W	1h	Reserved
7	VMUV_WARN_EN	R/W	0h	VM under voltage warn fault enable 0h = VM under voltage warning fault is disabled 1h = VM under voltage warning fault is enabled
6	RESERVED	R/W	1h	Reserved
5	RESERVED	R-0	0h	Reserved
4	RESERVED	R/W	1h	Reserved
3-2	RESERVED	R-0	0h	Reserved
1	RESERVED	R/W	1h	Reserved
0	RESERVED	R/W	1h	Reserved

8.6.9 DRVF_TCTRL Register (Offset = 13h) [Reset = 0155h]

DRVF_TCTRL is shown in 图 8-36 and described in 表 8-19.

Return to the [Summary Table](#).

图 8-36. DRVF_TCTRL Register

15	14	13	12	11	10	9	8
PARITY	RESERVED					RESERVED	
R/W-0h	R-0-0h					R/W-1h	
7	6	5	4	3	2	1	0
RESERVED		OCP_DEG		OCP_TBLANK		VMUV_WARN_TDG	
R/W-1h		R/W-1h		R/W-1h		R/W-1h	

表 8-19. DRVF_TCTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-10	RESERVED	R-0	0h	Reserved
9-8	RESERVED	R/W	1h	Reserved
7-6	RESERVED	R/W	1h	Reserved
5-4	OCP_DEG	R/W	1h	OCP deglitch time 0h = 0.3 μ s 1h = 0.6 μ s 2h = 0.9 μ s 3h = 1.2 μ s
3-2	OCP_TBLANK	R/W	1h	OCP blanking time 0h = 0.3 μ s 1h = 0.7 μ s 2h = 2 μ s 3h = 1.2 μ s
1-0	VMUV_WARN_TDG	R/W	1h	VM under voltage warning deglitch time 0h = 0.3 μ s 1h = 0.6 μ s 2h = 0.9 μ s 3h = 2 μ s

8.6.10 FLT_TCTRL Register (Offset = 16h) [Reset = 0003h]

FLT_TCTRL is shown in [图 8-37](#) and described in [表 8-20](#).

Return to the [Summary Table](#).

图 8-37. FLT_TCTRL Register

15	14	13	12	11	10	9	8
PARITY	RESERVED						
R/W-0h				R-0-0h			
7	6	5	4	3	2	1	0
RESERVED				SLOW_TRETRY		FAST_TRETRY	
R-0-0h				R/W-0h		R/W-3h	

表 8-20. FLT_TCTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-4	RESERVED	R-0	0h	Reserved
3-2	SLOW_TRETRY	R/W	0h	Retry time (typical) for slow recovery from fault condition 0h = 0.5s 1h = 1s 2h = 2s 3h = 5s
1-0	FAST_TRETRY	R/W	3h	Retry time (typical) for fast recovery from fault condition 0h = 0.5ms 1h = 1ms 2h = 2ms 3h = 5ms

8.6.11 FLT_CLR Register (Offset = 17h) [Reset = 0000h]

FLT_CLR is shown in [图 8-38](#) and described in [表 8-21](#).

Return to the [Summary Table](#).

图 8-38. FLT_CLR Register

15	14	13	12	11	10	9	8
RESERVED		RESERVED					
R/W-0h				R-0-0h			
7	6	5	4	3	2	1	0
RESERVED							FLT_CLR
R-0-0h							W-0h

表 8-21. FLT_CLR Register Field Descriptions

Bit	Field	Type	Reset	Description
15	RESERVED	R/W	0h	Reserved
14-1	RESERVED	R-0	0h	Reserved
0	FLT_CLR	W	0h	Clear latched faults 0h = No clear fault command is issued 1h = To clear the latched fault bits. This bit automatically resets after being written.

8.6.12 VMUV_WARN_THR Register (Offset = 18h) [Reset = 0000h]

VMUV_WARN_THR is shown in [图 8-39](#) and described in [表 8-22](#).

Return to the [Summary Table](#).

图 8-39. VMUV_WARN_THR Register

15	14	13	12	11	10	9	8
PARITY		RESERVED					
R/W-0h				R-0-0h			
7	6	5	4	3	2	1	0
VMUV_WARN_RTH				VMUV_WARN_FTH			
R/W-0h				R/W-0h			

表 8-22. VMUV_WARN_THR Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-8	RESERVED	R-0	0h	Reserved
7-4	VMUV_WARN_RTH	R/W	0h	VM under voltage warning rising threshold 0h = 5.62V 1h = 6.25V 2h = 6.87V 3h = 7.5V 4h = 8.12V 5h = 8.75V 6h = 9.37V 7h = 10.00V 8h = 10.62V 9h = 11.25V Ah = 11.87V Bh = 12.5V Ch = 13.75V Dh = 15.00V Eh = 16.25V Fh = 17.5V
3-0	VMUV_WARN_FTH	R/W	0h	VM under voltage warning falling threshold 0h = 5.4V 1h = 6.0V 2h = 6.6V 3h = 7.2V 4h = 7.8V 5h = 8.4V 6h = 9.0V 7h = 9.6V 8h = 10.2V 9h = 10.8V Ah = 11.4V Bh = 12.0V Ch = 13.2V Dh = 14.4V Eh = 15.6V Fh = 16.8V

8.6.13 PWM_CTRL Register (Offset = 20h) [Reset = 0000h]

PWM_CTRL is shown in 图 8-40 and described in 表 8-23.

Return to the [Summary Table](#).

图 8-40. PWM_CTRL Register

15	14	13	12	11	10	9	8
PARITY	RESERVED						
R/W-0h	R-0-0h						
7	6	5	4	3	2	1	0
RESERVED					SSC_DIS	PWM_MODE	
R-0-0h					R/W-0h	R/W-0h	

表 8-23. PWM_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-3	RESERVED	R-0	0h	Reserved
2	SSC_DIS	R/W	0h	Disable SSC on oscillator 0h = SSC enabled 1h = SSC disabled
1-0	PWM_MODE	R/W	0h	PWM mode selection 0h = 6x mode 1h = 6x direct mode 2h = 3x mode 3h = 3x direct mode

8.6.14 DRV_CTRL Register (Offset = 22h) [Reset = 0003h]

DRV_CTRL is shown in [图 8-41](#) and described in [表 8-24](#).

Return to the [Summary Table](#).

图 8-41. DRV_CTRL Register

15	14	13	12	11	10	9	8
PARITY	RESERVED			DLY_TARGET			
R/W-0h	R-0-0h			R/W-0h			
7	6	5	4	3	2	1	0
DLYCMP_EN	RESERVED					SLEW_RATE	
R/W-0h	R-0-0h					R/W-3h	

表 8-24. DRV_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-12	RESERVED	R-0	0h	Reserved
11-8	DLY_TARGET	R/W	0h	Delay Target : DLY_TARGET * 0.2μs
7	DLYCMP_EN	R/W	0h	Driver Delay Compensation enable 0h = Delay compensation disabled 1h = Delay compensation enabled
6-2	RESERVED	R-0	0h	Reserved
1-0	SLEW_RATE	R/W	3h	Slew rate settings 0h = Slew rate is 25 V/μs 1h = Slew rate is 50 V/μs 2h = Slew rate is 125 V/μs 3h = Slew rate is 200 V/μs

8.6.15 CSA_CTRL Register (Offset = 23h) [Reset = 0008h]

CSA_CTRL is shown in [图 8-42](#) and described in [表 8-25](#).

Return to the [Summary Table](#).

图 8-42. CSA_CTRL Register

15	14	13	12	11	10	9	8
PARITY	RESERVED						
R/W-0h				R-0-0h			
7	6	5	4	3	2	1	0
RESERVED				CSA_EN	RESERVED	CSA_GAIN	
R-0-0h				R/W-1h	R-0-0h	R/W-0h	

表 8-25. CSA_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-4	RESERVED	R-0	0h	Reserved
3	CSA_EN	R/W	1h	Enable CSA 0h = CSA is disabled 1h = CSA is enabled
2	RESERVED	R-0	0h	Reserved
1-0	CSA_GAIN	R/W	0h	CSA Gain settings 0h = CSA gain is 0.25 V/A 1h = CSA gain is 0.5 V/A 2h = CSA gain is 1 V/A 3h = CSA gain is 2 V/A

8.6.16 SYS_CTRL Register (Offset = 3Fh) [Reset = 5008h]

SYS_CTRL is shown in [图 8-43](#) and described in [表 8-26](#).

Return to the [Summary Table](#).

图 8-43. SYS_CTRL Register

15	14	13	12	11	10	9	8
PARITY	WRITE_KEY			RESERVED		RESERVED	RESERVED
R/W-0h	W-5h			R-0-0h		R/W-0h	R/W-0h
7	6	5	4	3	2	1	0
REG_LOCK	SPI_PEN	RESERVED		RESERVED	RESERVED		
R/W-0h	R/W-0h	R/W-0h		R/W-1h	R/W-0h		

表 8-26. SYS_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
15	PARITY	R/W	0h	Parity Bit if SPI_PEN is set to '1' otherwise reserved
14-12	WRITE_KEY	W	5h	0x5 : Write Key specific to this register.
11-10	RESERVED	R-0	0h	Reserved
9	RESERVED	R/W	0h	Reserved
8	RESERVED	R/W	0h	Reserved
7	REG_LOCK	R/W	0h	Register Lock Bit 0h = Registers Unlocked 1h = Registers Locked
6	SPI_PEN	R/W	0h	Parity Enable for SPI 0h = Parity Disabled 1h = Parity Enabled
5-4	RESERVED	R/W	0h	Reserved
3	RESERVED	R/W	1h	Reserved
2-0	RESERVED	R/W	0h	Reserved

9 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The DRV8317 can be used to drive brushless-DC motors. The following design procedure can be used to configure the DRV8317.

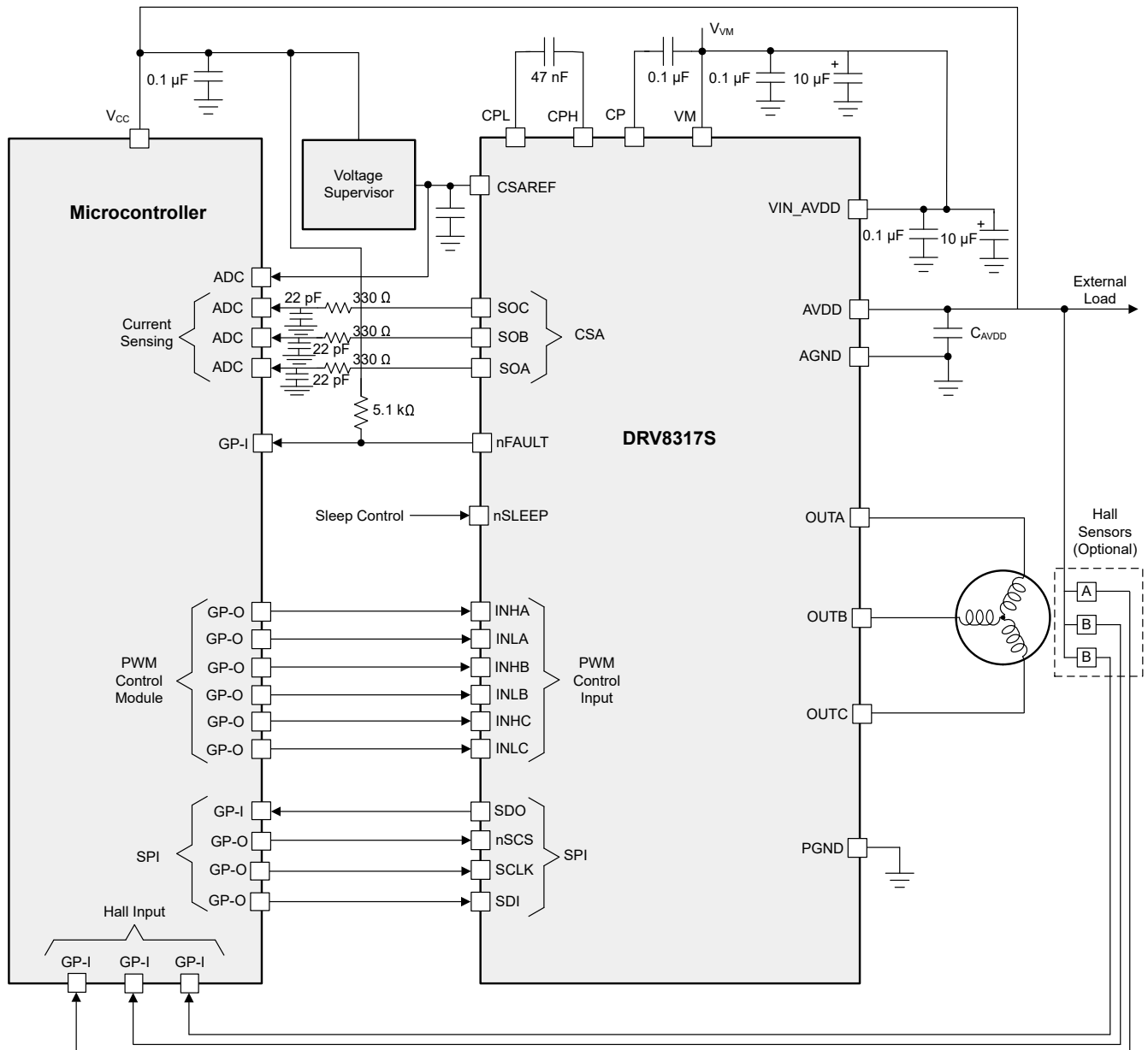


图 9-1. Application Schematics (DRV8317S)

9.2 Typical Applications

9.2.1 Three-Phase Brushless-DC Motor Control

In this application, the DRV8317 is used to drive a brushless-DC motor using PWMs from an external microcontroller.

9.2.1.1 Detailed Design Procedure

表 9-1 lists the example input parameters for the system design.

表 9-1. Design Parameters

DESIGN PARAMETERS	REFERENCE	EXAMPLE VALUE
Supply voltage	V_{VM}	12 V
Motor RMS current	I_{RMS}	2 A
Motor peak current	I_{PEAK}	3 A
PWM Frequency	f_{PWM}	50 kHz
Slew Rate Setting	SR	200 V/ μ s
VIN_AVDD supply voltage	V_{VIN_AVDD}	12 V
CSA reference voltage	V_{CSA_REF}	3.0 V
System ambient temperature	T_A	-20°C to +50°C

9.2.1.1.1 Motor Voltage

Brushless-DC motors are typically rated for a certain voltage (for example, 5V or 12V). The DRV8317 allows for a range of possible operating voltages from 4.5-V to 20-V.

9.2.1.2 Driver Propagation Delay and Dead Time

The propagation delay is defined as the time taken for changing input logic edges INHx and INLx (whichever changes first, if MCU dead time is added) to change the half-bridge output voltage (OUTx). Driver propagation delay (t_{PD}) and dead time (t_{dead}) are specified with a typical and maximum value, but not with a minimum value. This is because the propagation delay can be smaller than typical depending on the direction of current at the OUTx pin during synchronous switching. Driver propagation delay and dead time can be more than typical values due to slower internal turn-on of the high-side or low-side internal MOSFETs to avoid parasitic dV/dt coupling.

For more information and examples of how propagation delay and dead time differs for input PWM and output configurations, refer to [Delay and Dead Time in Integrated MOSFET Drivers](#).

The dead time from the external microcontroller's (MCU) PWM inputs (INHx, INLx) can be used as an extra precaution in addition to the DRV8317 internal shoot-through (cross conduction) protection. If the MCU dead time is less than the DRV8317 driver dead time, actual output (OUTx voltage) dead time will be decided by the DRV8317 dead time (t_{DEAD}). If the MCU dead time is larger than the driver dead time, actual output (OUTx voltage) dead time will be decided by the MCU dead time.

A summary of the DRV8317 delay times with respect to synchronous inputs INHx and INLx, OUTx current direction, and MCU dead time are listed in 表 9-2.

表 9-2. Summary of Delay Times in DRV8317 Depending on Logic Inputs and Output Current Direction

OUTx Current Direction	INHx	INLx	Propagation Delay (t_{PD})	Dead Time (t_{DEAD})	Inserted MCU Dead Time ($t_{DEAD(MCU)}$)	
					$t_{DEAD(MCU)} \leq t_{DEAD}$	$t_{DEAD(MCU)} > t_{DEAD}$
Out of OUTx	Rising	Falling	$\leq t_{PD} (max)$	$\leq t_{DEAD} (max)$	Output dead time $\leq t_{DEAD}$	Output dead time = $t_{DEAD(MCU)}$
	Falling	Rising	$\leq t_{PD} (typ.)$	$\leq t_{DEAD} (typ.)$	Output dead time $\leq t_{DEAD}$	Output dead time < $t_{DEAD(MCU)}$

表 9-2. Summary of Delay Times in DRV8317 Depending on Logic Inputs and Output Current Direction
(续)

OUTx Current Direction	INHx	INLx	Propagation Delay (t _{PD})	Dead Time (t _{DEAD})	Inserted MCU Dead Time (t _{DEAD(MCU)})	
					t _{DEAD(MCU)} ≤ t _{DEAD}	t _{DEAD(MCU)} > t _{DEAD}
Into OUTx	Rising	Falling	≤ t _{PD} (typ.)	≤ t _{DEAD} (typ.)	Output dead time ≤ t _{DEAD} (typ.)	Output dead time < t _{DEAD(MCU)}
	Falling	Rising	≤ t _{PD} (max)	≤ t _{DEAD} (max)	Output dead time ≤ t _{DEAD} (max)	Output dead time = t _{DEAD(MCU)}

9.2.1.3 Delay Compensation

Differences in delays of dead time and propagation delay can cause mismatch in the output timings of PWMs, which can lead to duty cycle distortion. In order to accommodate differences in propagation delay between the conditions mentioned in 表 9-2, DRV8317 integrates a delay compensation feature.

Delay compensation is used to match delay times for currents going into and out of phase (OUTx) by adding a variable delay time (t_{var}) to match a preset target delay time equal to the propagation delay plus driver dead time (t_{PD} + t_{DRV_DEAD}). This (t_{var}) setting is automatically configured by the DRV8317 when the DLYCMP_EN bit is set to 1b.

9.2.1.4 Current Sensing and Output Filtering

The SOx pins are typically sampled by an analog-to-digital converter in the MCU to calculate the phase current. Phase current information is used for closed-loop control such as Field-Oriented Control (FOC).

An example calculation for phase current is shown in 方程式 3.

$$SOx = V_{REF}/2 + G_{CSA} * I_{OUTx} \quad (3)$$

For example, in a system with VREF = 3-V, CSA gain = 0.5 V/A, and a SOx voltage of 1.2-V, phase current (I_{OUTx}) = -0.6A.

Sometimes high frequency noise can appear at the SOx signals based on voltage ripple at VREF, added inductance at the SOx traces, or routing of SOx traces near high frequency components. It is recommended to add a low-pass RC filter close to the MCU with cut-off frequency at least 10 times the PWM switching frequency for trapezoidal commutation and 100 times the PWM switching frequency for sinusoidal commutation to filter high frequency noise. A recommended RC filter is 330-ohms, 22-pF to add minimal parallel capacitance to the ADC and current mirroring circuitry without increasing the settling time of the CSA output.

The cutoff frequency for the low-pass RC filter is in 方程式 4.

$$f_c = \frac{1}{2\pi RC} \quad (4)$$

9.2.1.5 Application Curves



图 9-2. Device Power up with VM (VM, nFAULT, nSLEEP, AVDD)



图 9-3. Device Power up with nSLEEP (VM, nFAULT, nSLEEP, AVDD)

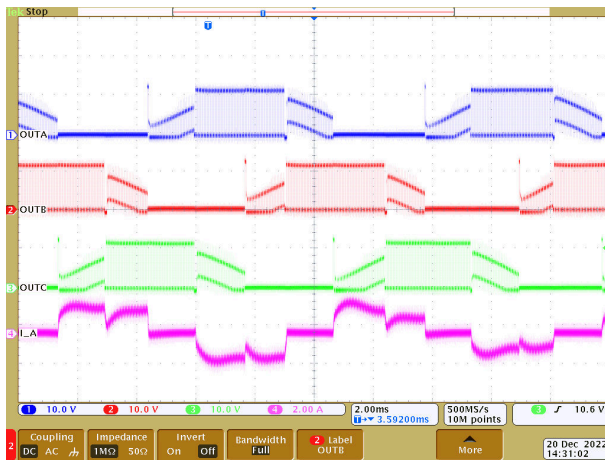


图 9-4. Driver PWM Operation (OUTA, OUTB, OUTC, I_A)

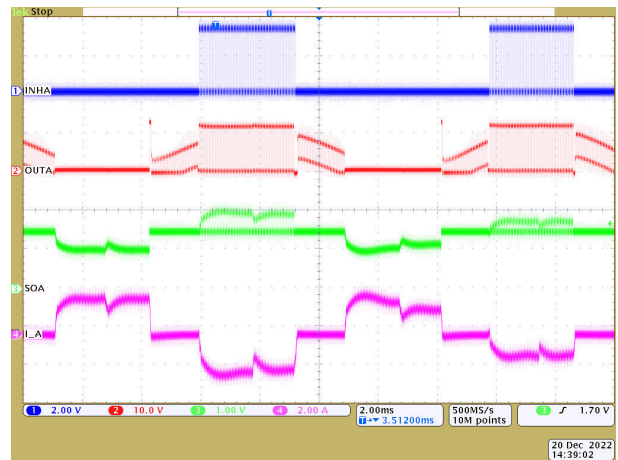


图 9-5. Driver PWM Operation with Current Sense Feedback (INHA, OUTA, SOA, I_A)

9.3 Alternate Applications

The DRV8317 can be used to drive brushed-DC motors and solenoid loads. The following design procedure can be used to configure the DRV8317.

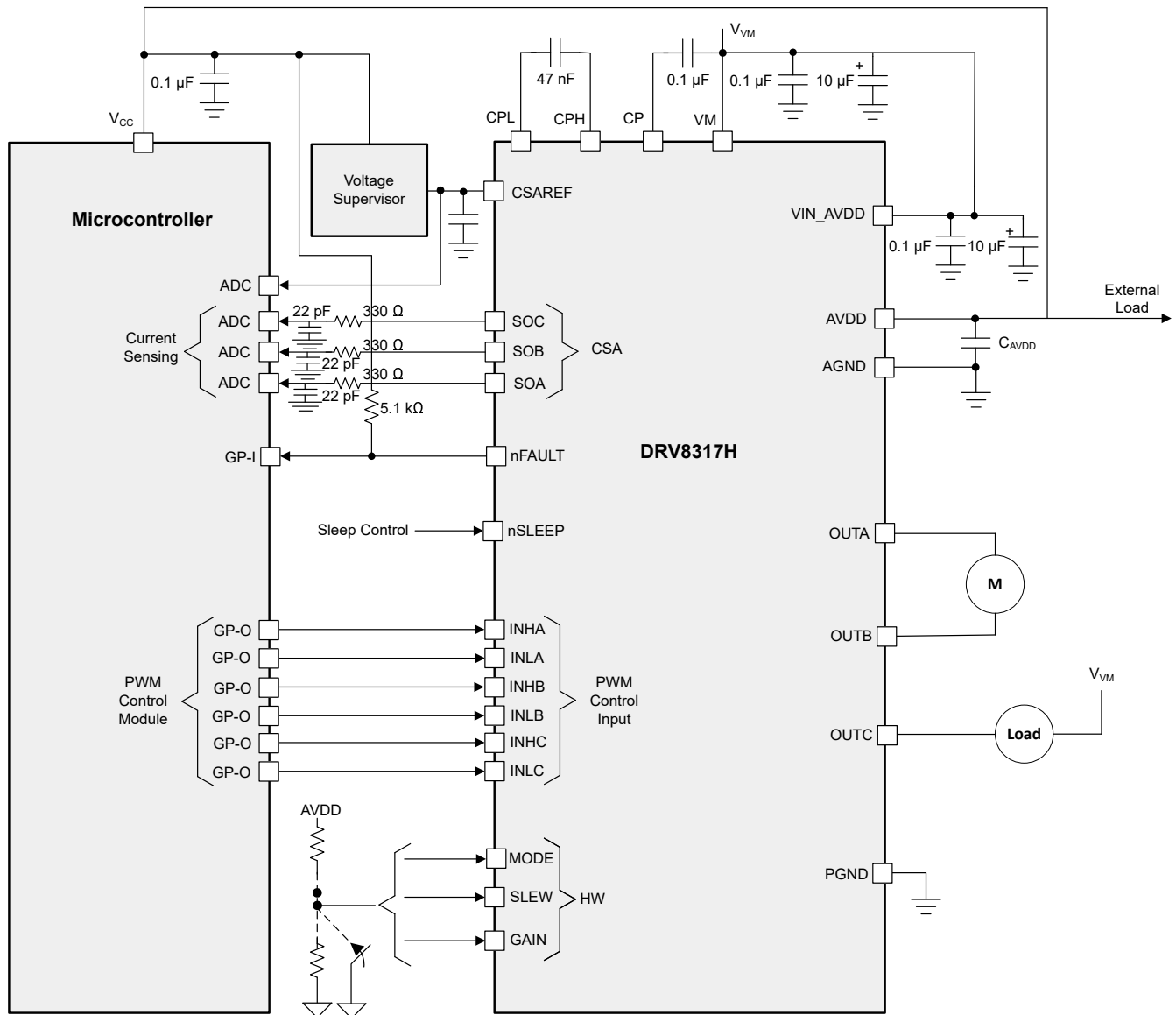


图 9-6. Application Schematics (DRV8317H) - Brushed-DC and Solenoid Load Drive Block Diagram

6x PWM mode or 3x PWM mode can be used to drive brushed-DC and/or solenoid loads depending on the application. A Brushed-DC motor can be connected to two OUTx phases to create an integrated full H-bridge configuration to drive the motor in both direction.

Solenoid loads can be connected from OUTx to VM or GND to use the DRV8317 as a push-pull driver in 6x PWM or 3x PWM mode. When the load is connected from OUTx to GND, the HS MOSFET sources current into the solenoid, and the LS MOSFET acts as a recirculation diode to recirculate current from the solenoid. When the load is connected from OUTx to VM, the LS MOSFET sink current from the solenoid to GND, and the HS MOSFET acts as a recirculation diode to recirculate current from the solenoid.

10 Power Supply Recommendations

10.1 Bulk Capacitance

Having an appropriate local bulk capacitance is an important factor in motor drive system design. It is generally beneficial to have more bulk capacitance, while the disadvantages are increased cost and physical size.

The amount of local capacitance needed depends on a variety of factors, including:

- The highest current required by the motor system
- The capacitance and current capability of the power supply
- The amount of parasitic inductance between the power supply and motor system
- The acceptable voltage ripple
- The type of motor used (brushed dc, brushless DC, stepper)
- The motor braking method

The inductance between the power supply and the motor drive system limits the rate current can change from the power supply. If the local bulk capacitance is too small, the system responds to excessive current demands or dumps from the motor with a change in voltage. When adequate bulk capacitance is used, the motor voltage remains stable and high current can be quickly supplied.

The data sheet generally provides a recommended value, but system-level testing is required to determine the appropriate sized bulk capacitor.

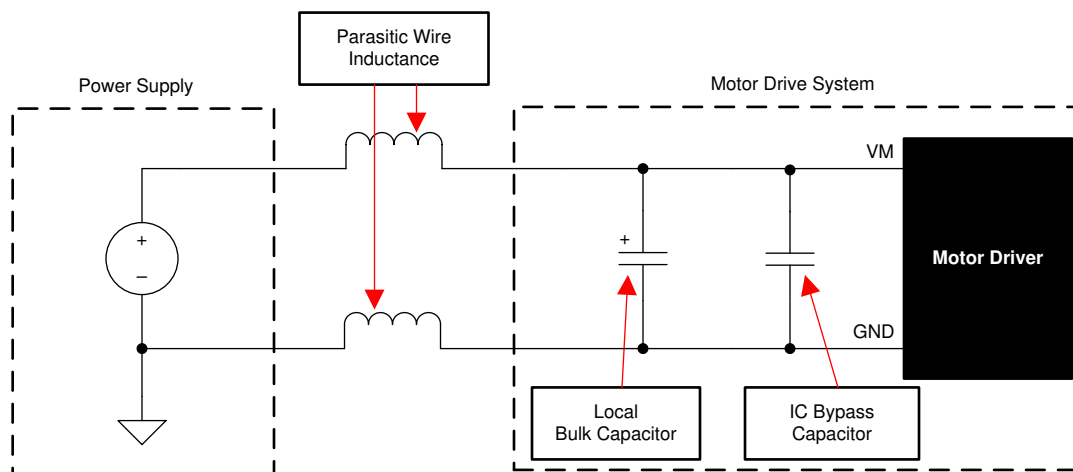


图 10-1. Example Setup of Motor Drive System With External Power Supply

The voltage rating for bulk capacitors should be higher than the operating voltage, to provide margin for cases when the motor transfers energy to the supply.

11 Layout

11.1 Layout Guidelines

The bulk capacitor should be placed to minimize the distance of the high-current path through the motor driver device. The connecting metal trace widths should be as wide as possible, and numerous vias should be used when connecting PCB layers. These practices minimize inductance and allow the bulk capacitor to deliver high current.

Small-value capacitors should be ceramic, and placed closely to device pins including, AVDD, charge pump, CSAREF, VINAVDD and VM.

The high-current device outputs should use wide metal traces.

To reduce noise coupling and EMI interference from large transient currents into small-current signal paths, grounding should be partitioned between PGND and AGND. TI recommends connecting all non-power stage circuitry (including the thermal pad) to AGND to reduce parasitic effects and improve power dissipation from the device. Ensure grounds are connected through net-ties to reduce voltage offsets and maintain gate driver performance. A common ground plane can also be used for PGND and AGND to minimize inductance in the grounding, but it is recommended to place motor switching outputs as far away from analog and digital signals so motor noise does not couple into the analog and digital circuits.

The device thermal pad should be soldered to the PCB top-layer ground plane. Multiple vias should be used to connect to a large bottom-layer ground plane. The use of large metal planes and multiple vias helps dissipate the heat that is generated in the device.

To improve thermal performance, maximize the ground area that is connected to the thermal pad ground across all possible layers of the PCB. Using thick copper pours can lower the junction-to-air thermal resistance and improve thermal dissipation from the die surface.

 [图 11-1](#) shows a recommended layout example.

11.2 Layout Example

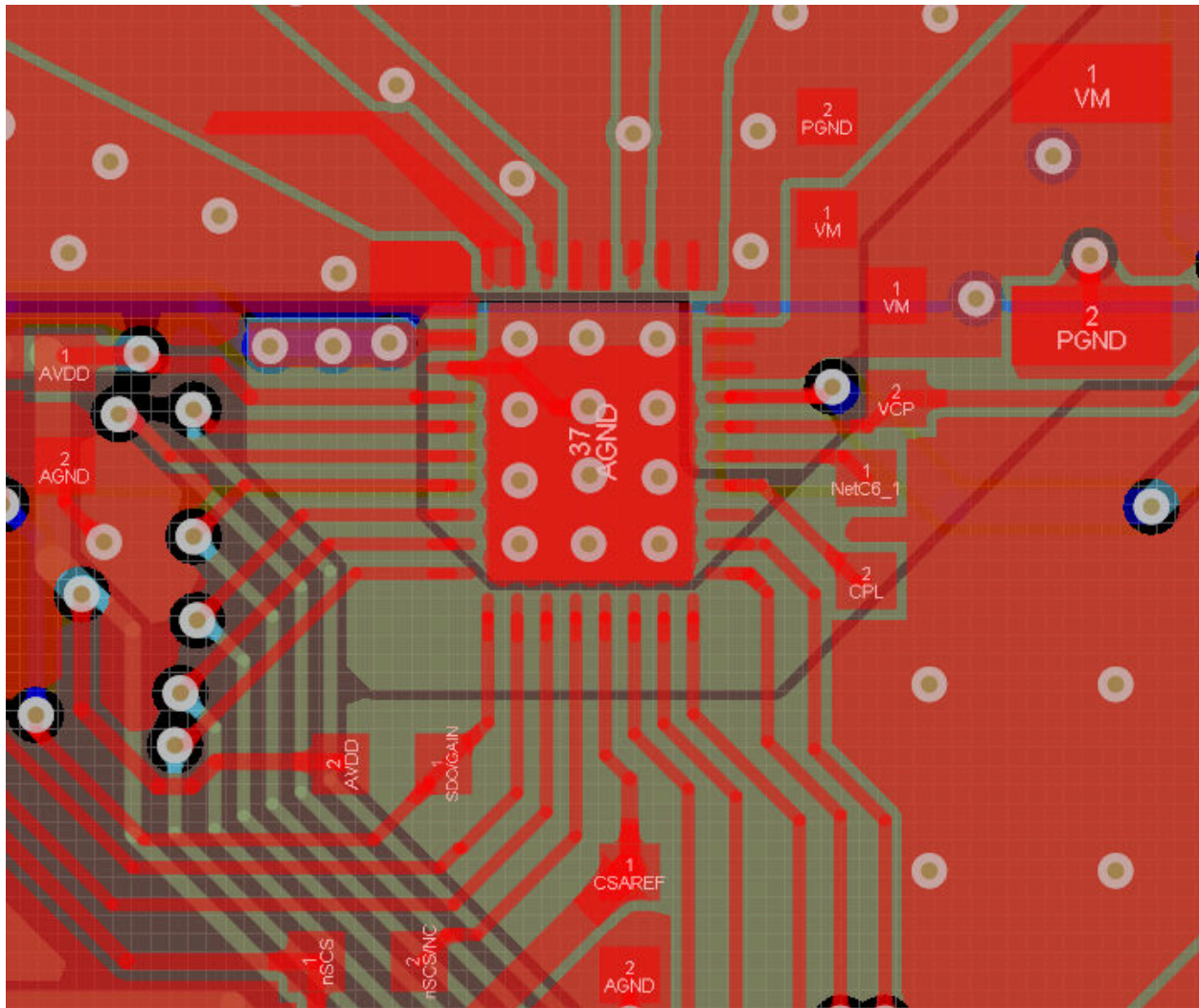


图 11-1. Recommended Layout Example

11.3 Thermal Considerations

The DRV8317 has thermal shutdown (OTS) as previously described. A die temperature in excess of 145°C (min.) can disable the device until the temperature drops to a safe level.

Any tendency of the device to enter thermal shutdown is an indication of excessive power dissipation, insufficient heatsinking, or too high an ambient temperature.

11.3.1 Power Dissipation and Junction Temperature Estimation

Power Dissipation

The power loss in DRV8317 include standby losses, LDO losses, FET conduction and switching losses, and diode losses. The FET conduction loss dominates the total power dissipation in DRV8317. At start-up and fault conditions, the output current is much higher than normal current; remember to take these peak currents and their duration into consideration. The total device dissipation is the power dissipated in each of the three half bridges added together. The maximum amount of power that the device can dissipate depends on ambient temperature and heatsinking. Note that $R_{DS,ON}$ increases with temperature, so as the device heats, the power dissipation increases. Take this into consideration when designing the PCB and heatsinking.

A summary of equations for calculating each loss is listed in [表 11-1](#) for trapezoidal control and field-oriented control.

表 11-1. DRV8317 Power Losses for Trapezoidal and Field-oriented Control

Loss type	Trapezoidal control	Field-oriented control
Standby power	$P_{standby} = V_{VM} \times I_{VMS}$	
AVDD LDO	$P_{LDO} = (V_{VIN_AVDD} - V_{AVDD}) \times I_{AVDD}$	
FET conduction	$P_{CON} = 2 \times (I_{PK(trap)})^2 \times R_{DS,ON(TJ)}$	$P_{CON} = 3 \times (I_{RMS(FOC)})^2 \times R_{DS,ON(TJ)}$
FET switching	$P_{SW} = I_{PK(trap)} \times V_{PK(trap)} \times t_{rise/fall} \times f_{PWM}$	$P_{SW} = 3 \times I_{RMS(FOC)} \times V_{PK(FOC)} \times t_{rise/fall} \times f_{PWM}$
Diode (dead time)	$P_{diode} = 2 \times I_{PK(trap)} \times V_{F(diode)} \times t_{DEAD} \times f_{PWM}$	$P_{diode} = 6 \times I_{RMS(FOC)} \times V_{F(diode)} \times t_{DEAD} \times f_{PWM}$

备注

$R_{DS,ON(TJ)}$ is the on-state resistance of a single FET at operating junction temperature.

Junction Temperature Estimation

To calculate the junction temperature of the die from power losses, use [方程式 5](#). Note that the thermal resistance $R_{\theta JA}$ depends on PCB configuration such as the numbers of PCB layers, copper thickness, ground plane area and the PCB size.

$$T_J(^{\circ}C) = P_{LOSS}(W) \times R_{\theta JA}(^{\circ}C/W) + T_A(^{\circ}C) \quad (5)$$

Refer to [BLDC integrated MOSFET thermal calculator](#) for estimating the approximate device power dissipation and junction temperature at different use cases.

12 Device and Documentation Support

12.1 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.2 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

12.3 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

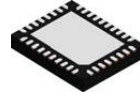
ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

12.4 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most-current data available for the designated device. This data is subject to change without notice and without revision of this document. For browser-based versions of this data sheet, see the left-hand navigation pane.

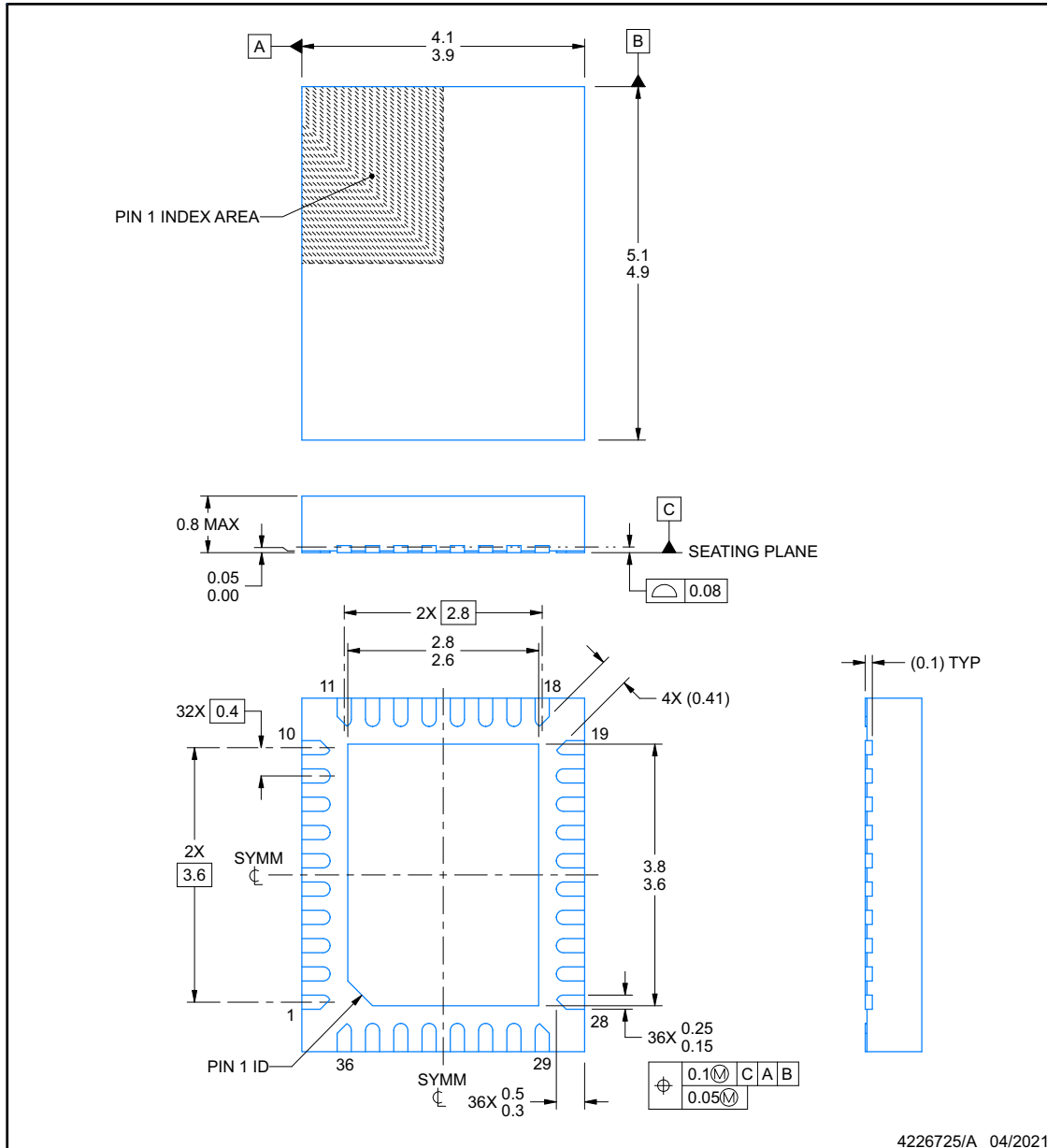


PACKAGE OUTLINE

REE0036A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

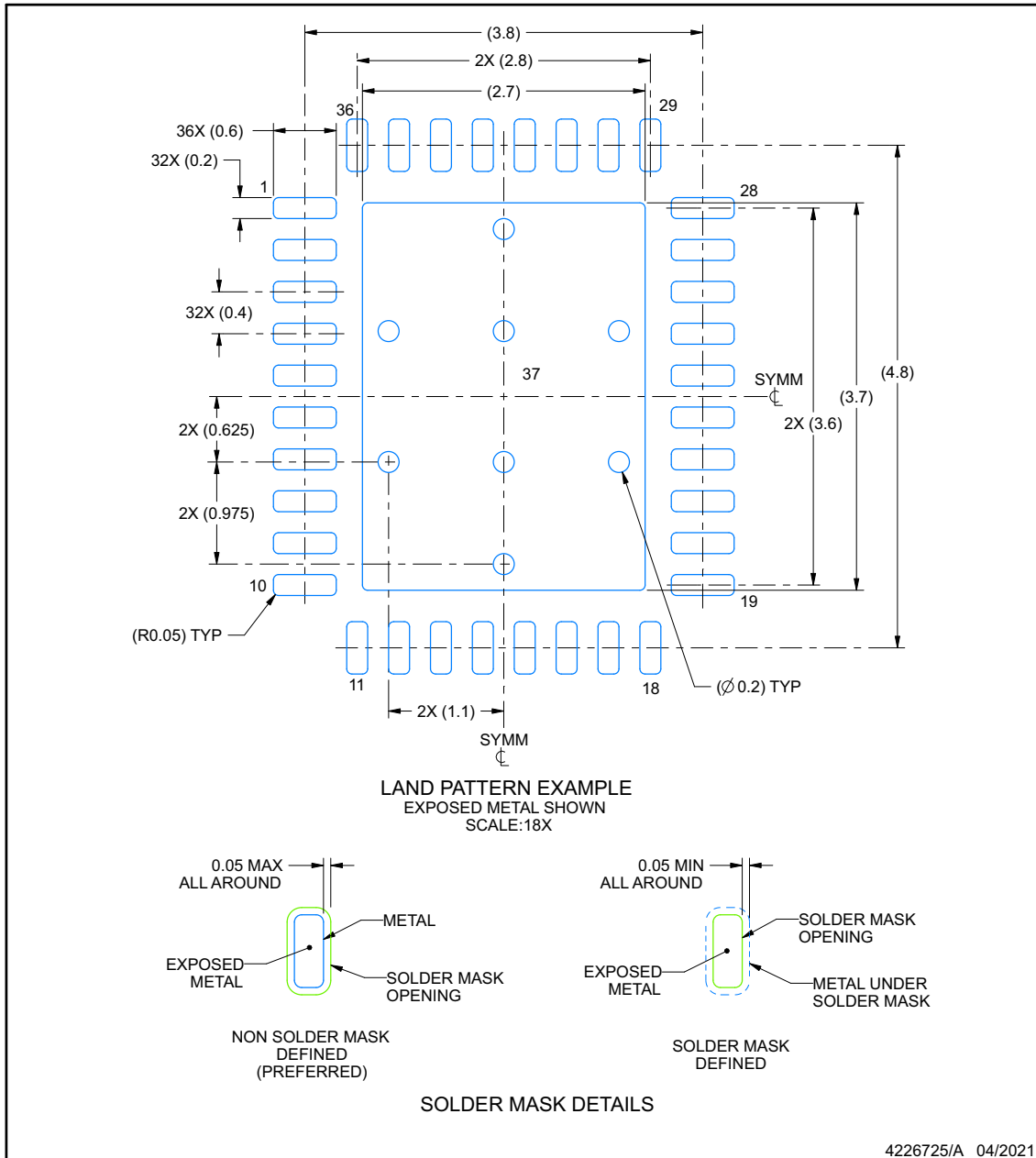
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

REE0036A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

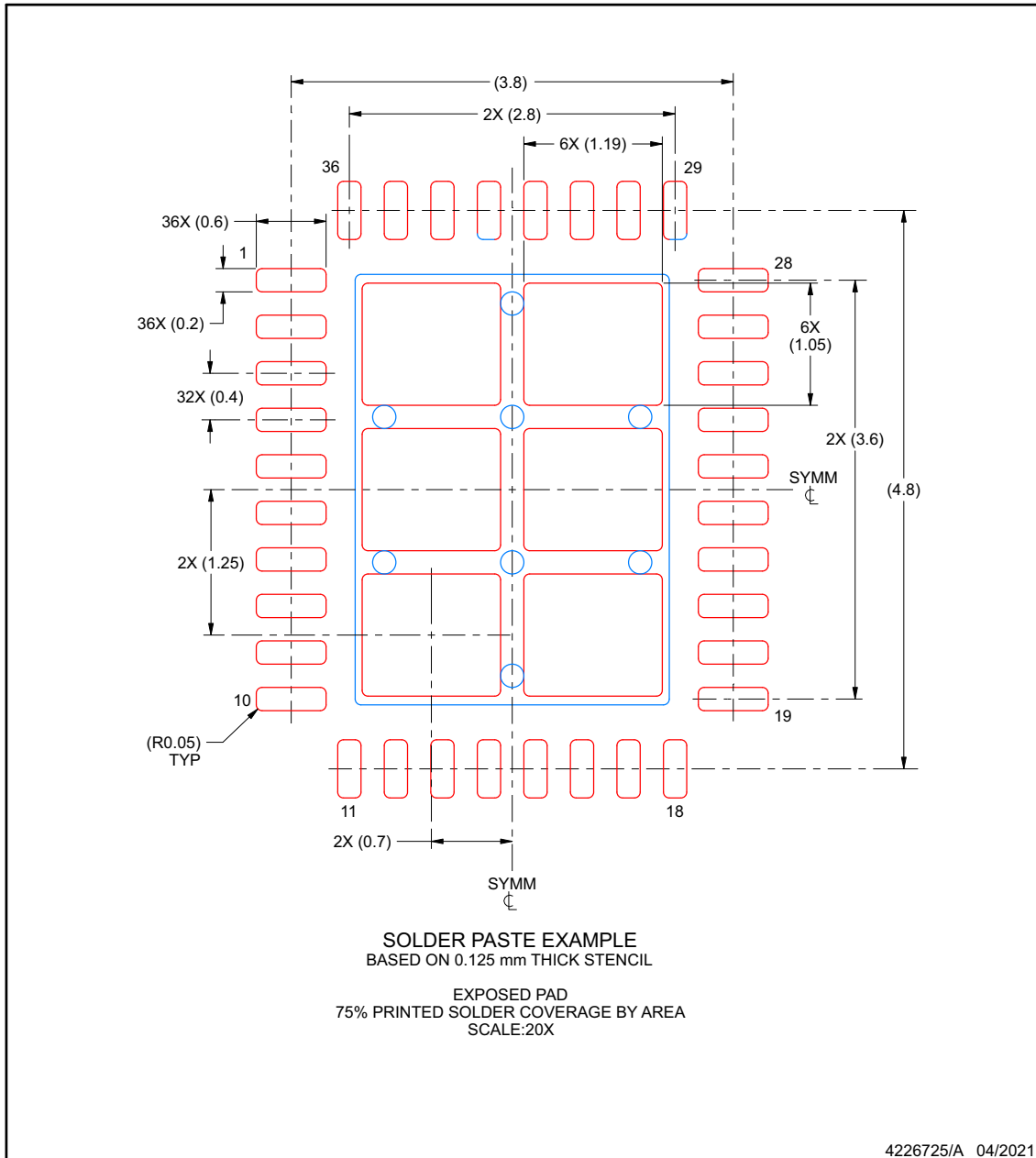
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

REE0036A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DRV8317HREER	ACTIVE	WQFN	REE	36	5000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DRV 8317H	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

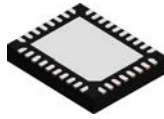
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

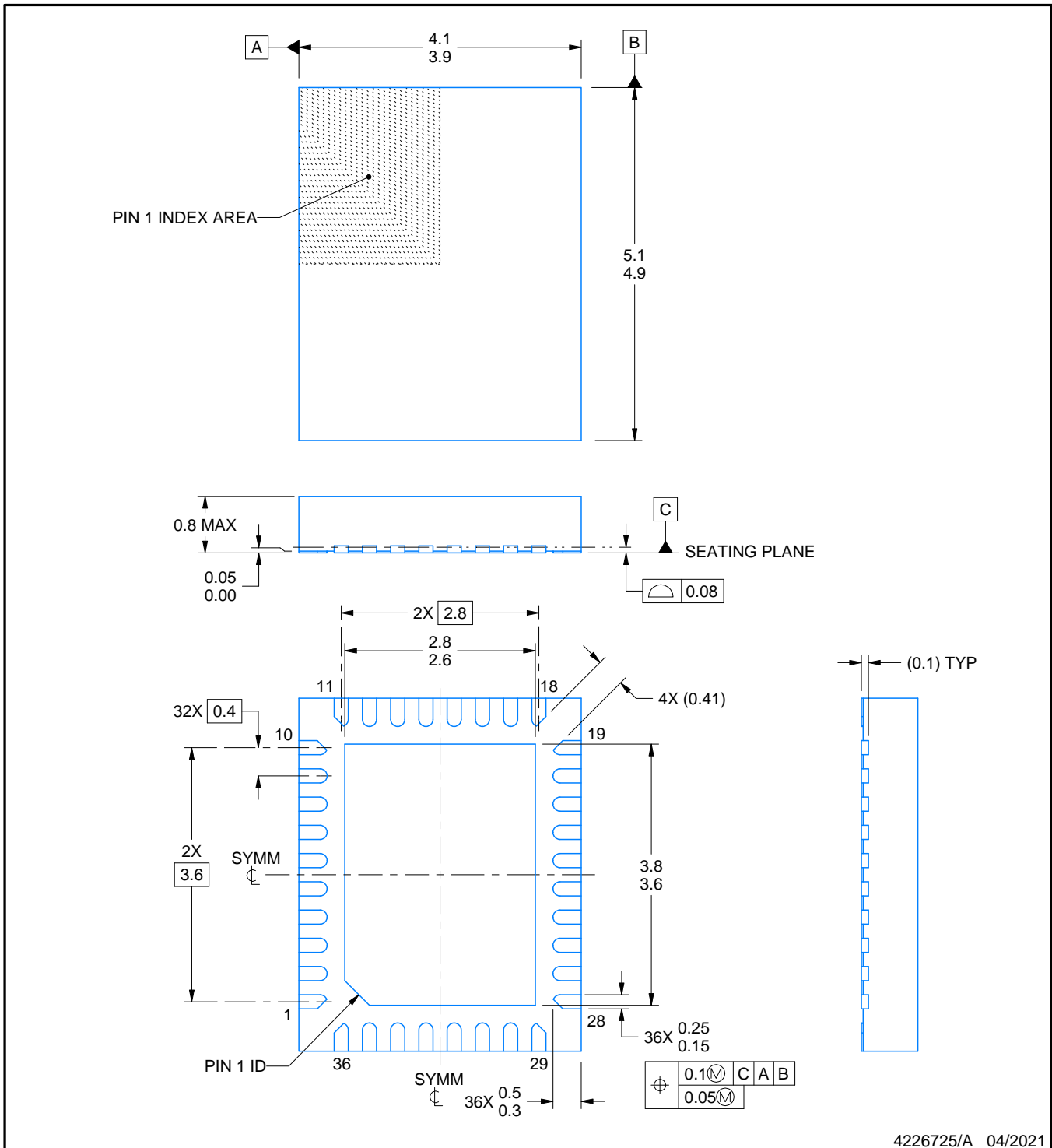
REE0036A



PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4226725/A 04/2021

NOTES:

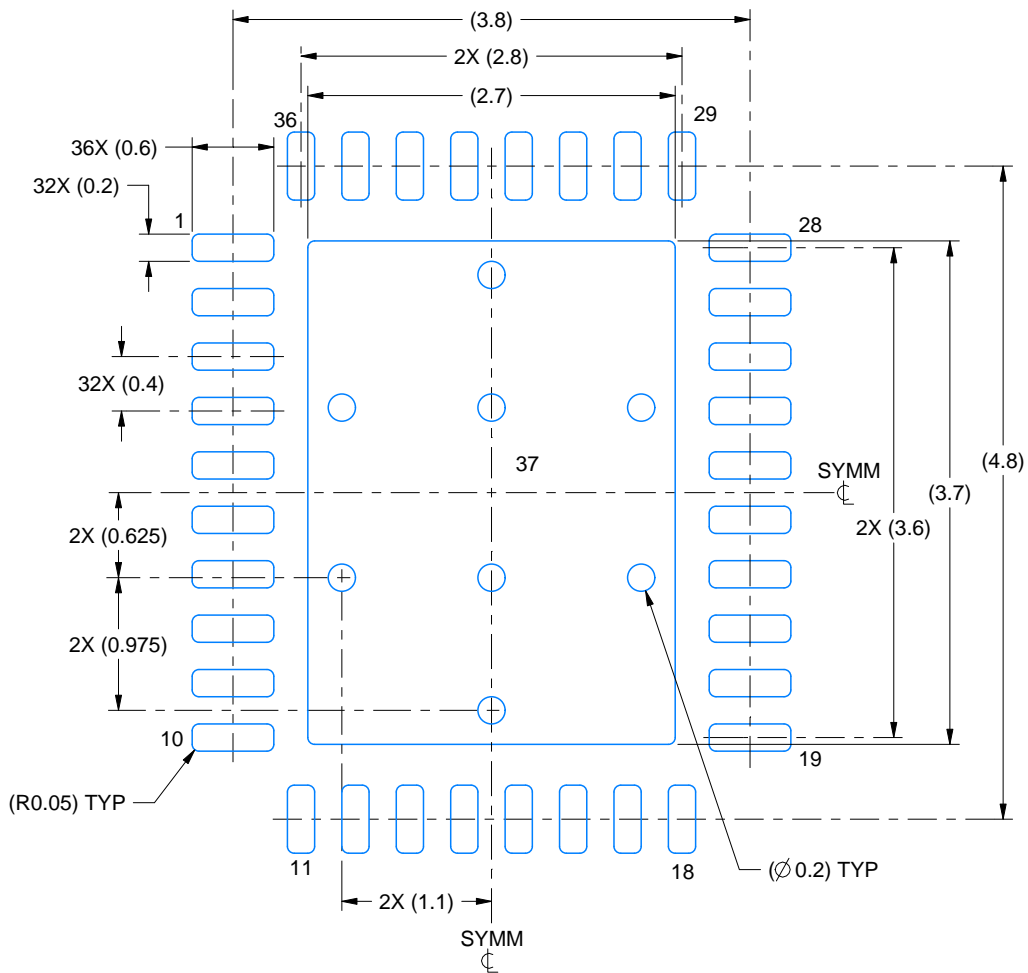
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

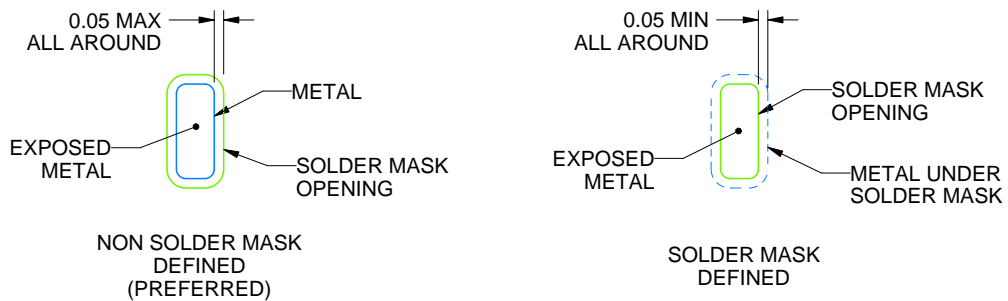
REE0036A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4226725/A 04/2021

NOTES: (continued)

- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2024，德州仪器 (TI) 公司